

Gas phase epitaxy

Example: AlGaInN growth by MOVPE

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Examples of questions

How does pressure in the reactor influence the growth rate of AlGaAs?

How does total flow influence the Mg incorporation into AlGaN?

How does temperature influence formation of vacancies in InGaN?

How do growth breaks between InGaAs and GaAs influence the homogeneity of the quantum wells?

Examples of questions

~~How does pressure in the reactor influence the growth rate of AlGaAs?~~

~~How does total flow influence the Mg incorporation into AlGaN?~~

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~~How do growth breaks between InGaAs and GaAs influence the homogeneity of the quantum wells?~~

How **pressure**
temperature
NH3 flow
TEGa flow
TMIn flow
H2 flow
N2 flow
Growth breaks
etc influence the InGaN QW properties?

Properties: chemical composition, thickness, defect concentration, optical and electrical properties. etc

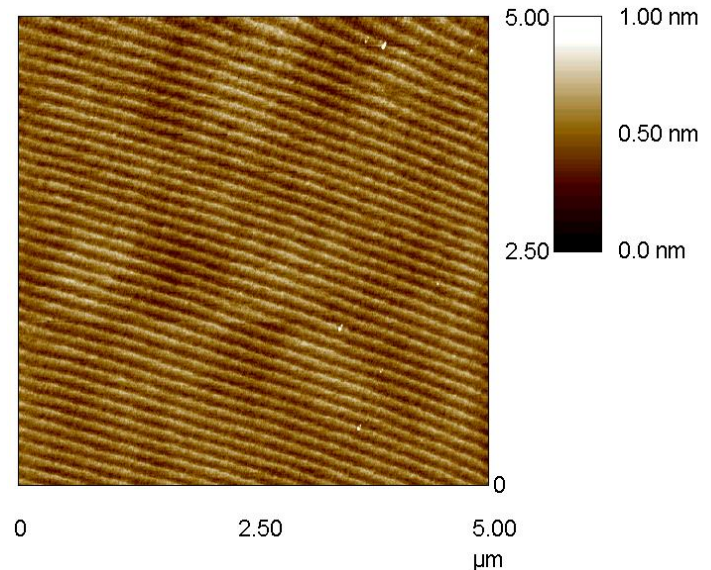
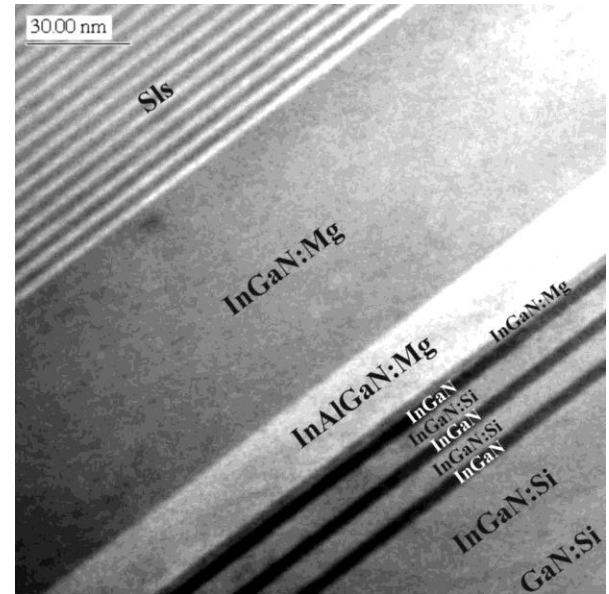
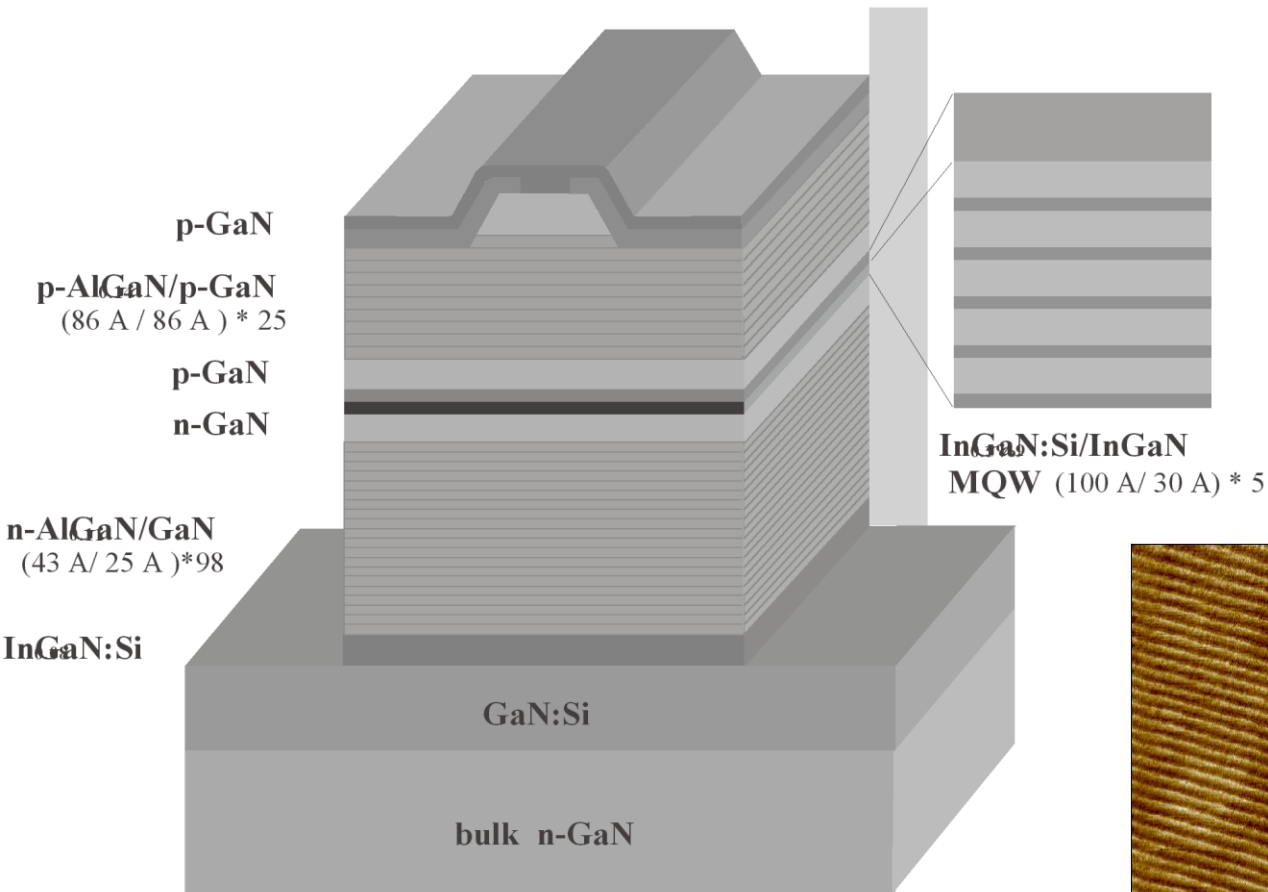
Growth parameters in MOVPE are not independent to each other.

If we wished to test all combinations for only 4 values, we would have to do 4^{10} experiments= 1 000 000

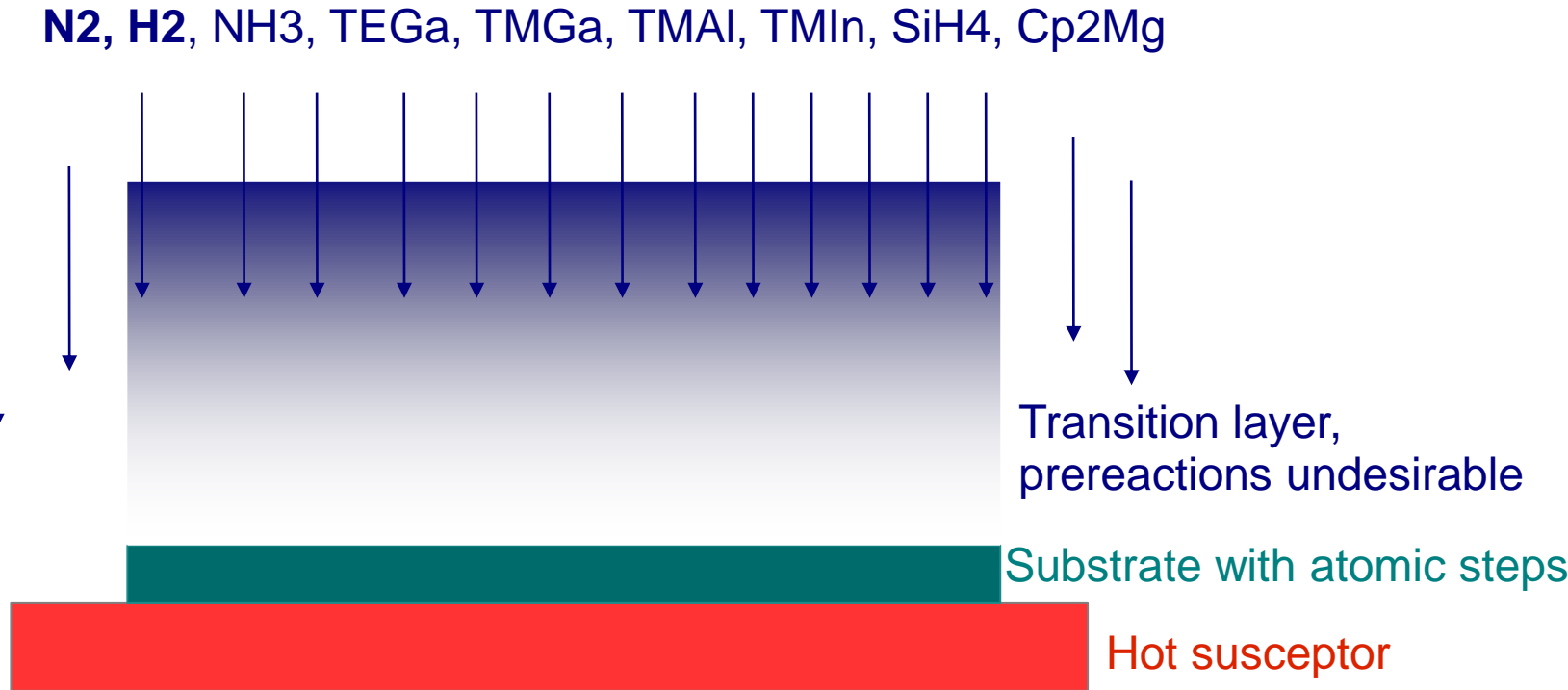
Outline

- 1. Effectiveness of atom incorporation into GaN, AlGaN, InGaN**
- 2. Example of influence of hydrogen on InGaN growth**
- 3. Examples of how properties of the epi layers can be modified by growth of other layers.**

What do we wish to grow? For example, laser diode epi structure.



MOVPE growth of nitride semiconductors

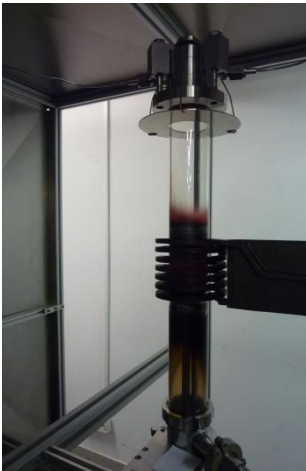


As a result, we have a layer which has certain:

- * chemical composition
- * thickness
- * morphology
- * uniformity

1. Effectiveness of atom incorporation into GaN, AlGa_N, InGa_N

MOVPE reactors used



Home made (HM)
2000 growth runs

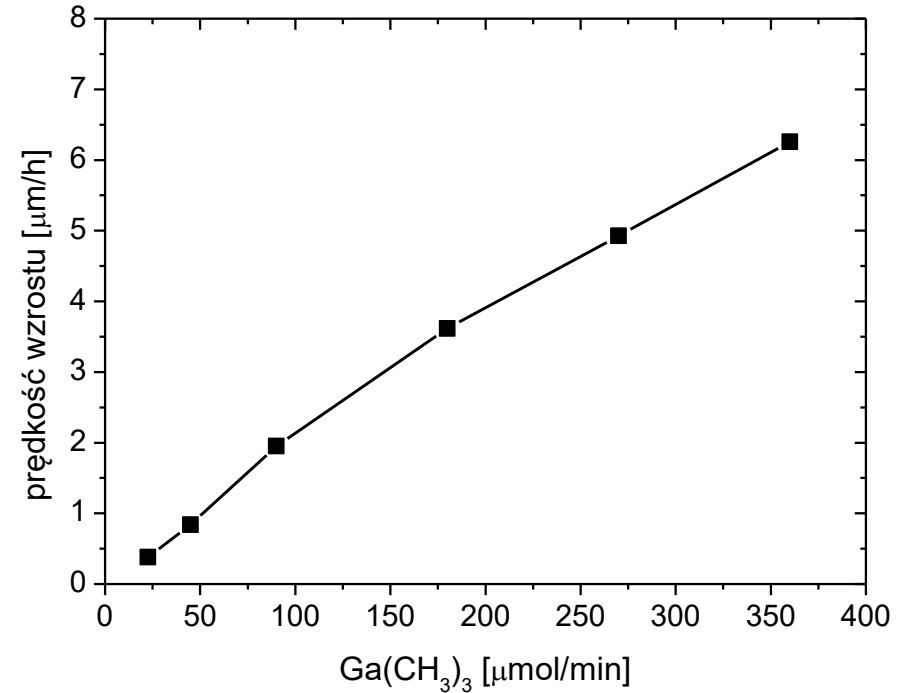
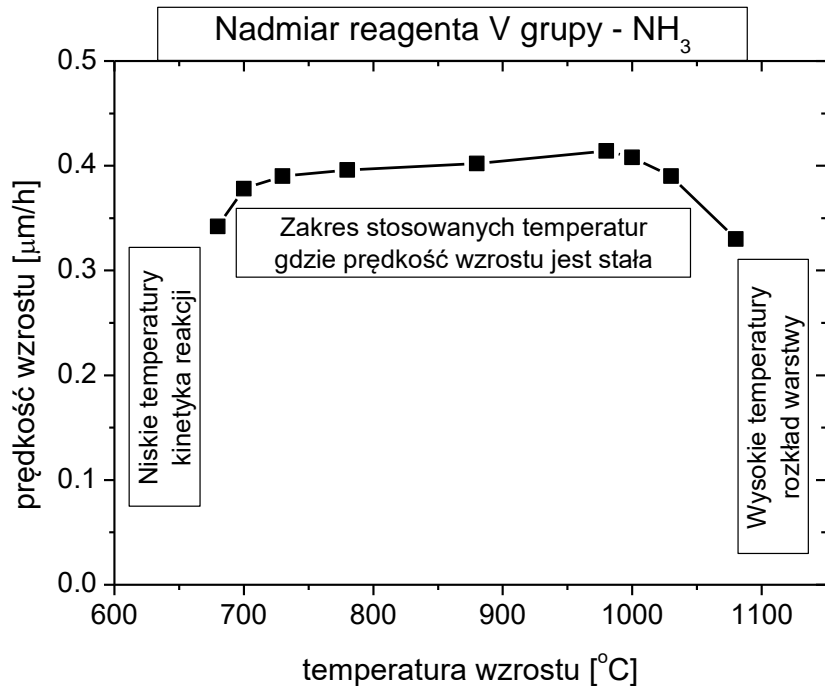


CCS Aixtron
6000 growth runs



High Pressure (HP)
200 growth runs

Effectiveness of Ga incorporation into GaN vs temperature and TMGa flow in HM



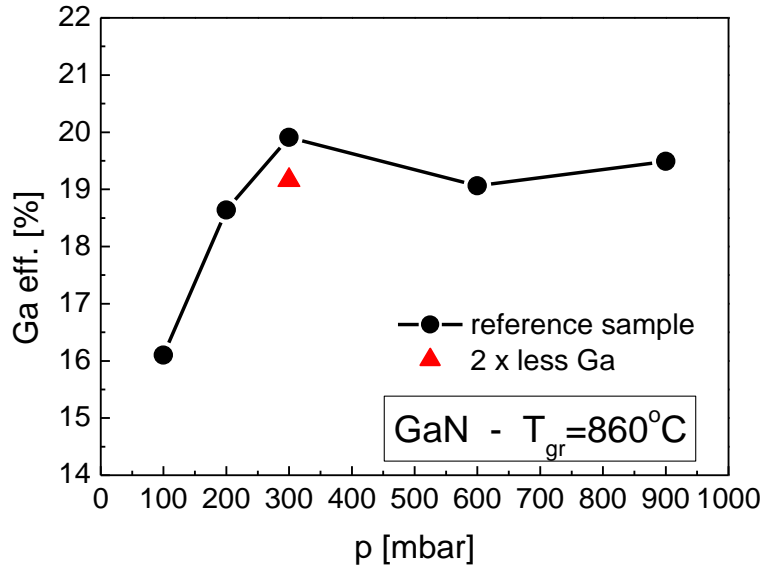
Growth rate proportional to TMGa or TEGa flow

Low temperature – low ammonia decomposition

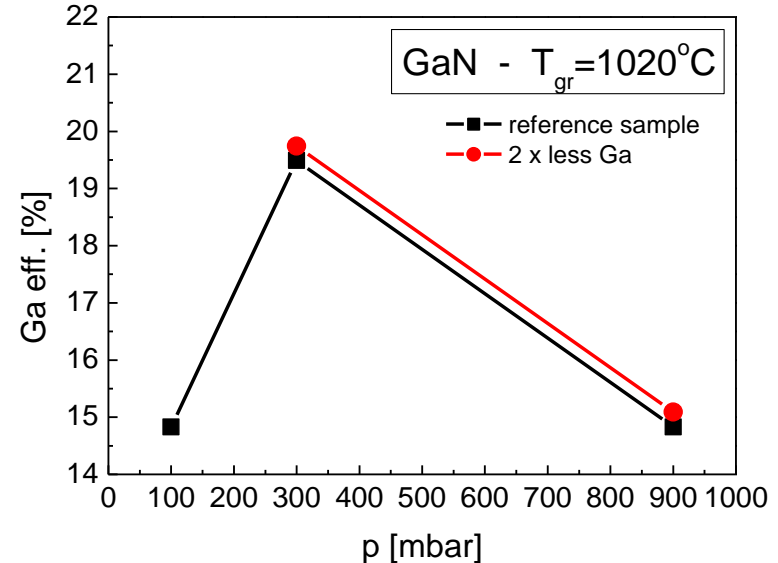
High temperature- decomposition

Effectiveness of Ga incorporation into GaN vs pressure

Efficiency= number of atoms in gas phase/ number of atoms incorporated into the epi layer



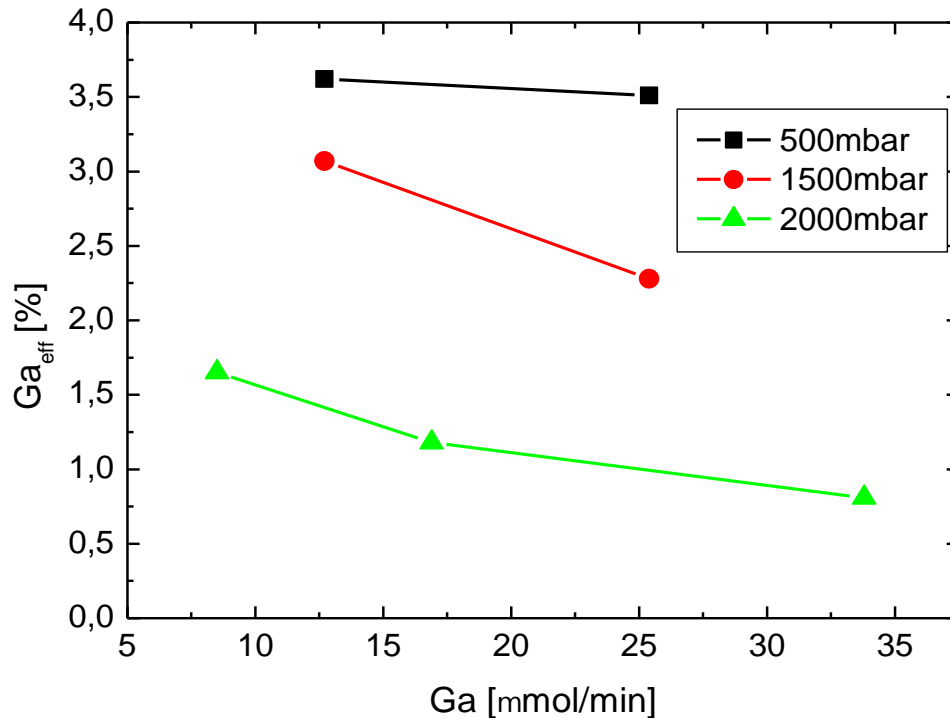
At low pressure, the Ga atoms are blown away from the surface.



At high pressure and temperature, the rate of pre-reactions increase which prevents Ga incorporation

Efficiency of Ga incorporation independent on amount of TEGa

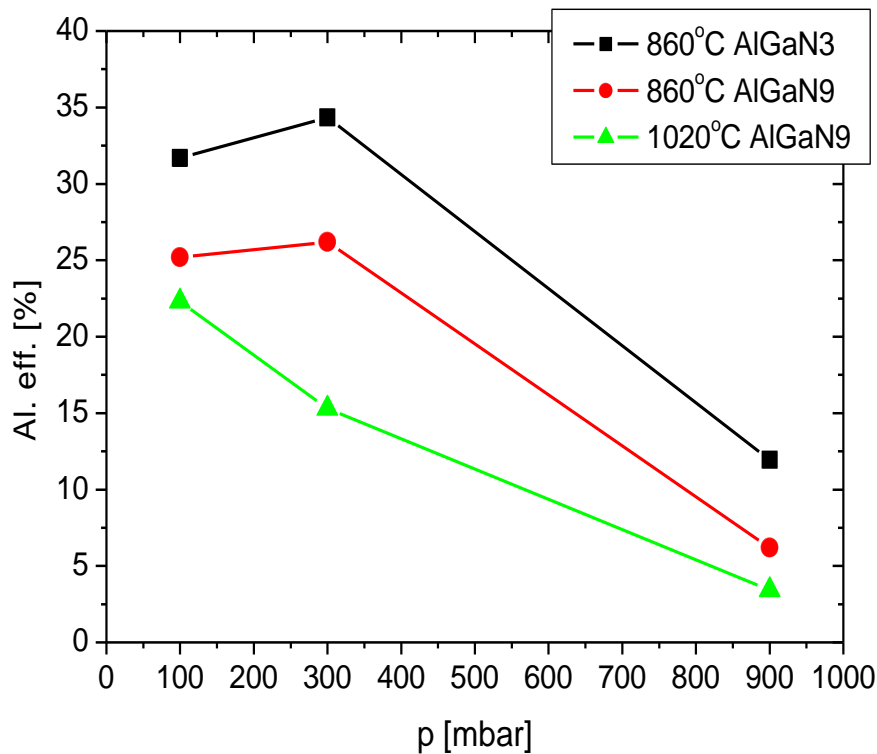
Efficiency of Ga incorporation into GaN in HP



Much lower efficiencies of Ga incorporation than in HM and CCS

At high pressure, prereactions lower the Ga-incorporation efficiency

Efficiency of Al incorporation into AlGaN in HM



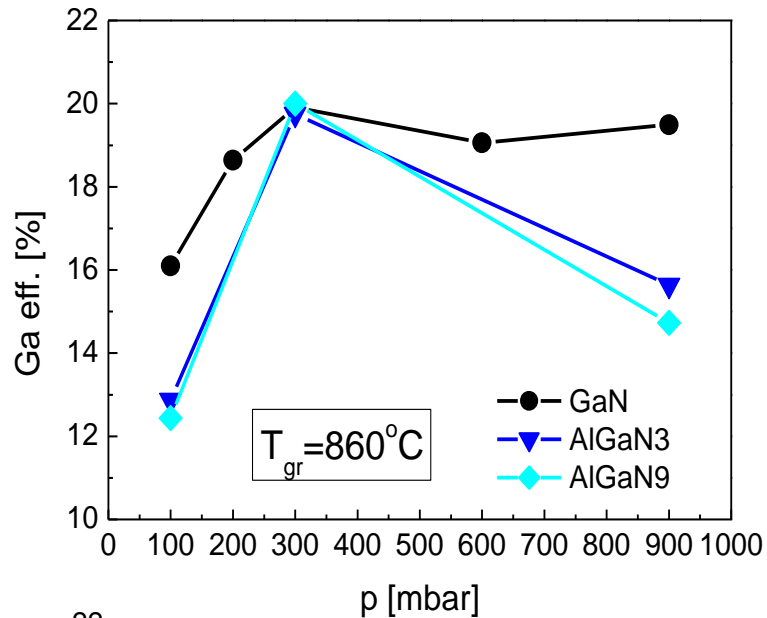
Efficiency of Al incorporation falls down with TMAI flow increase

Prereactions rate higher than in the case of GaN

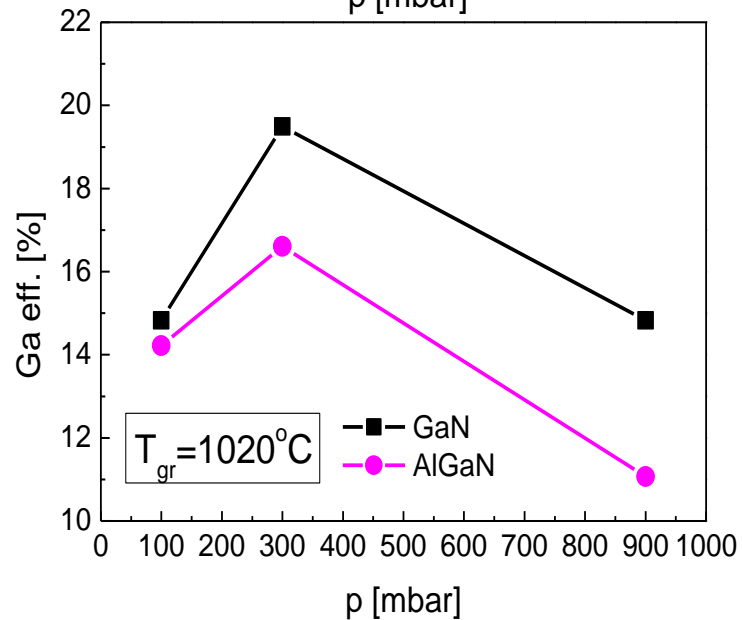
More prereactions at high temperature and pressure

3 sccm of TMAI
9 sccm of TMAI

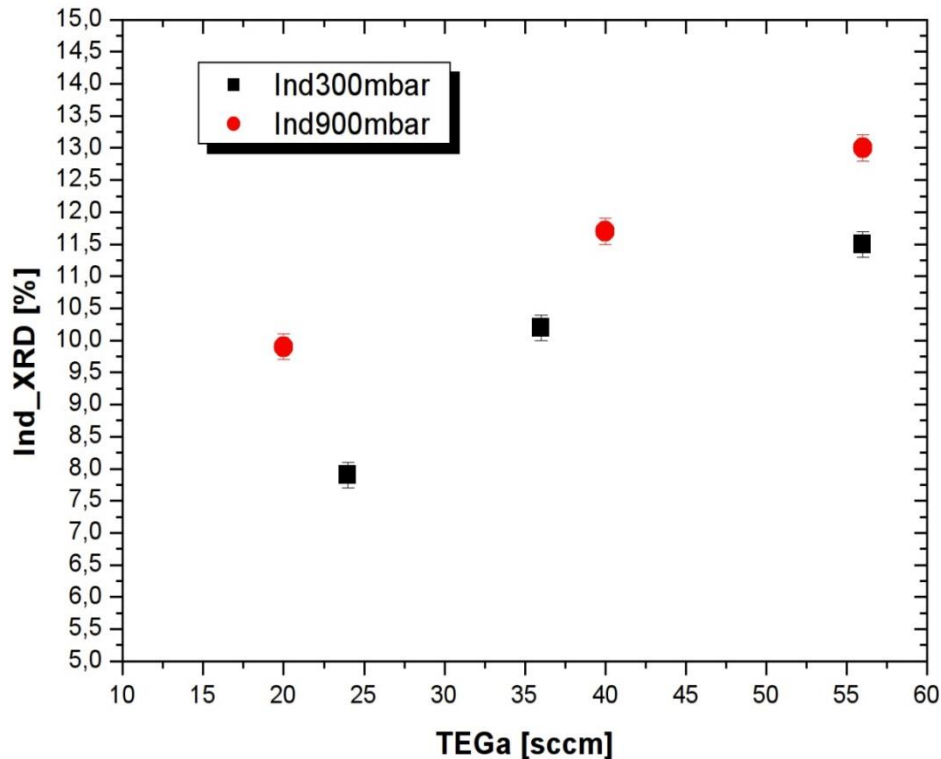
Efficiency of Ga incorporation into AlGaN in HM



Prereacted TMAI and NH₃ molecules block Ga incorporation



Efficiency of In incorporation into InGaN versus TEGa (growth rate) flow in HM

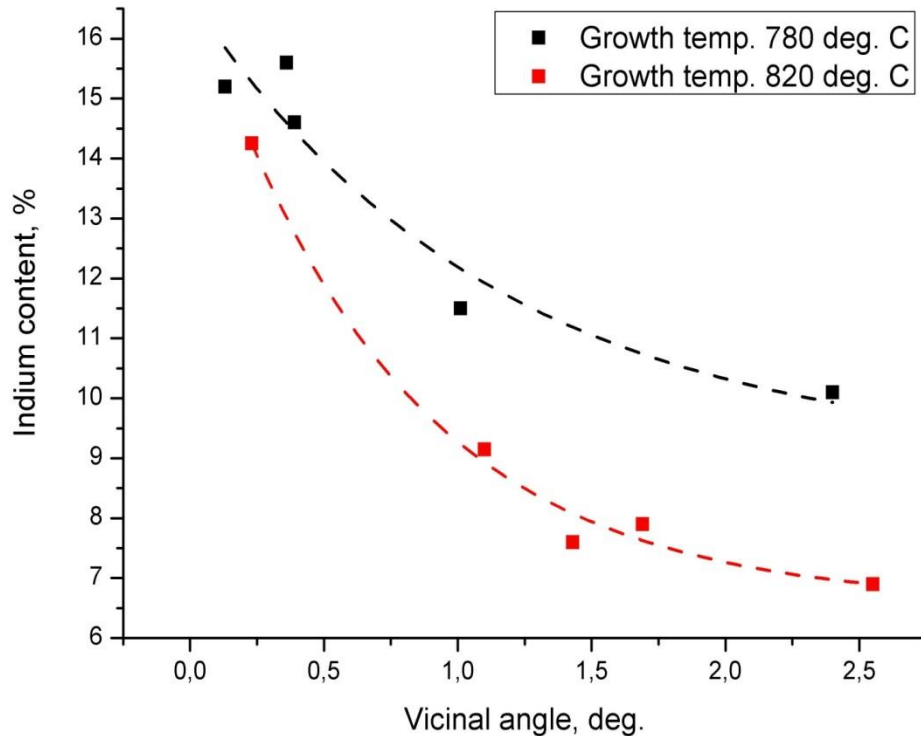


More Ga source in the gas phase,
but more In in InGaN solid phase.

More indium at elevated pressure.

In atoms to be incorporated must
be surrounded by Ga atoms

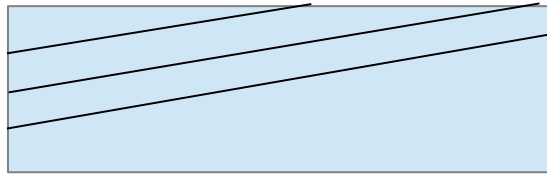
In incorporation into InGaN layers versus GaN substrate off-orientation



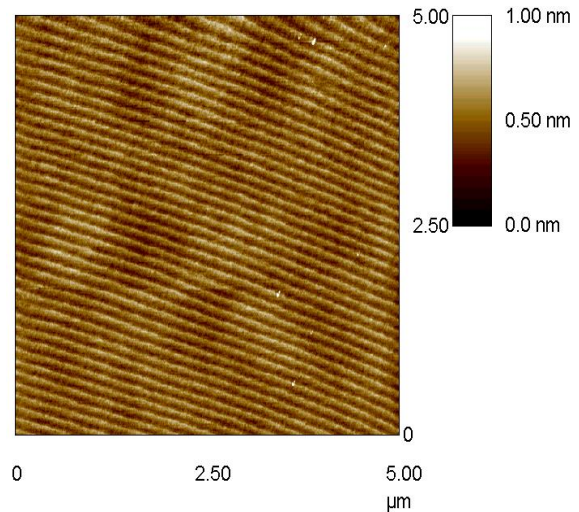
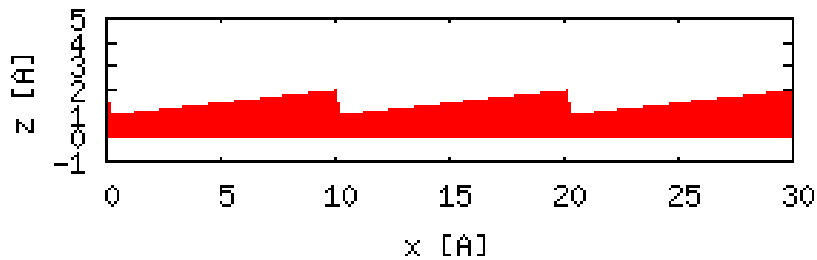
If we have bad morphology (steps are not identical), we deal with In inhomogeneous incorporation

GaN substrate off-orientation

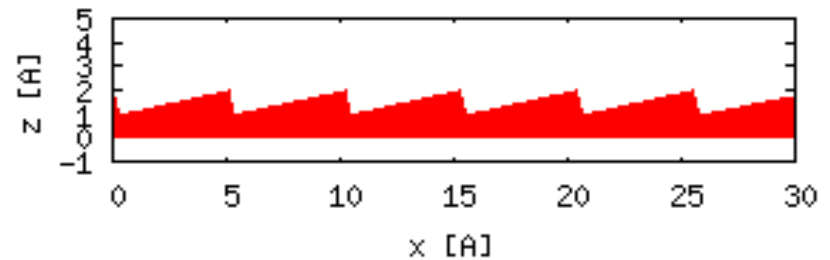
- The steps flow slower
- **Many AlGaN and InGaN parameters are strongly influenced**



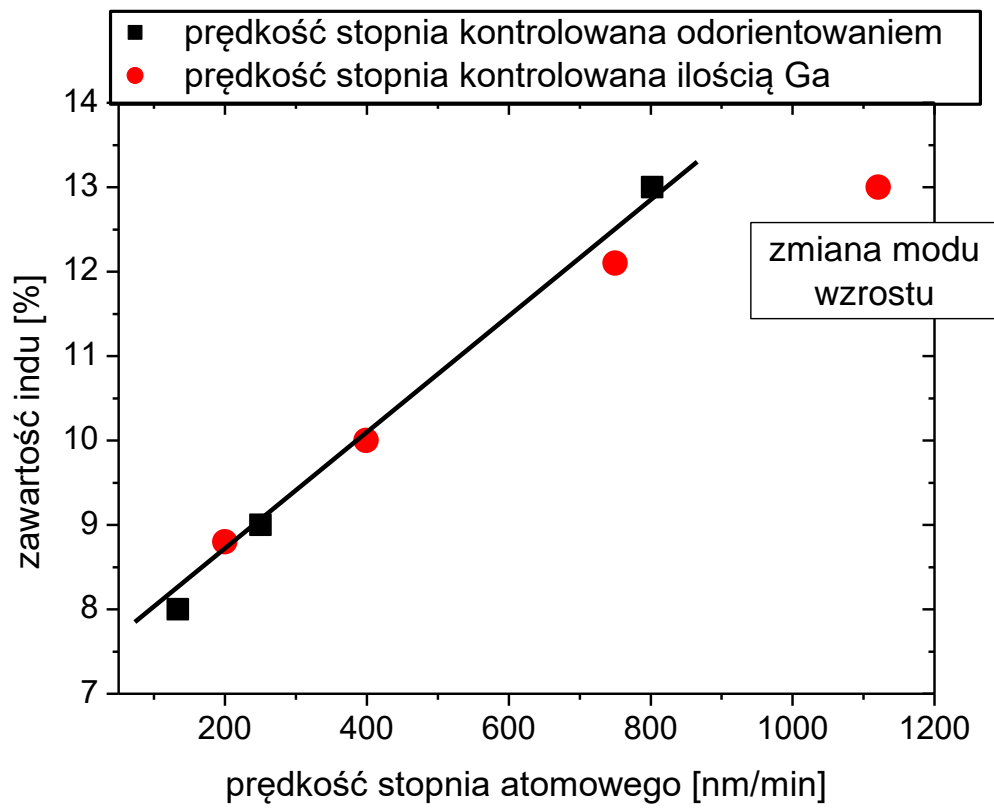
Low misorientation - fast atomic steps



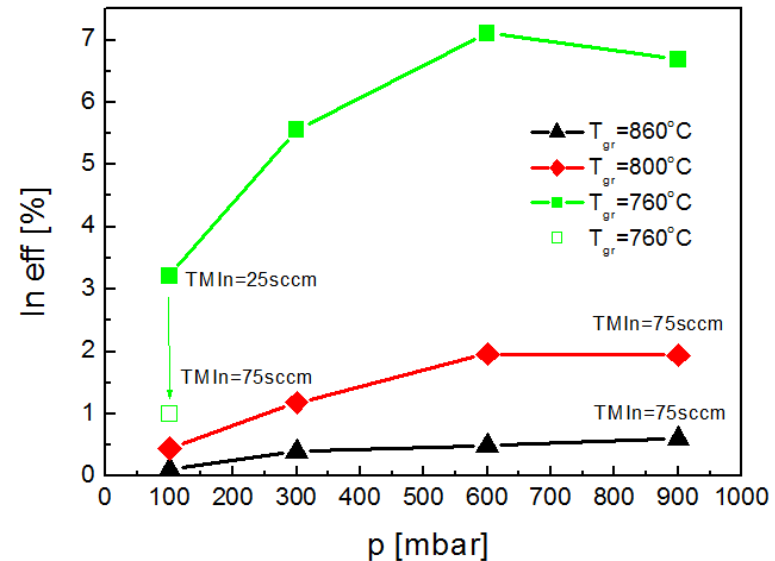
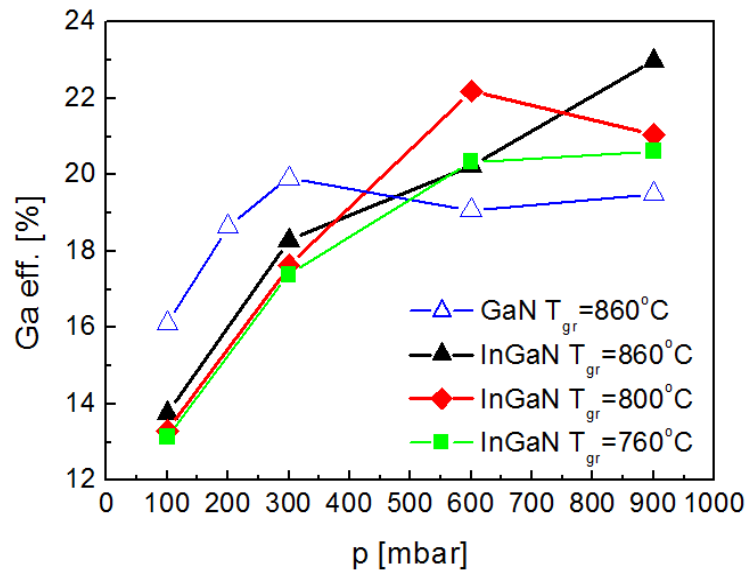
Higher misorientation - slower atomic steps



Incorporation into InGaN versus velocity of the steps in step-flow growth



Efficiency of Ga and In incorporation into InGaN in HM

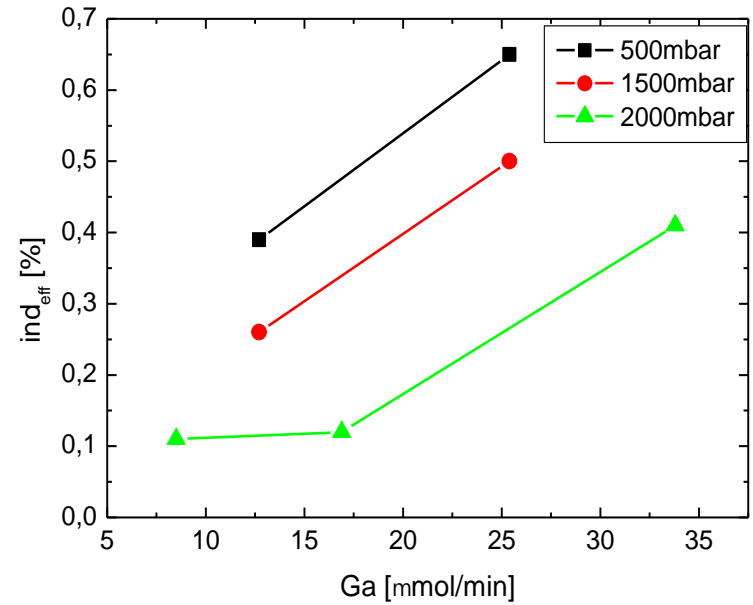
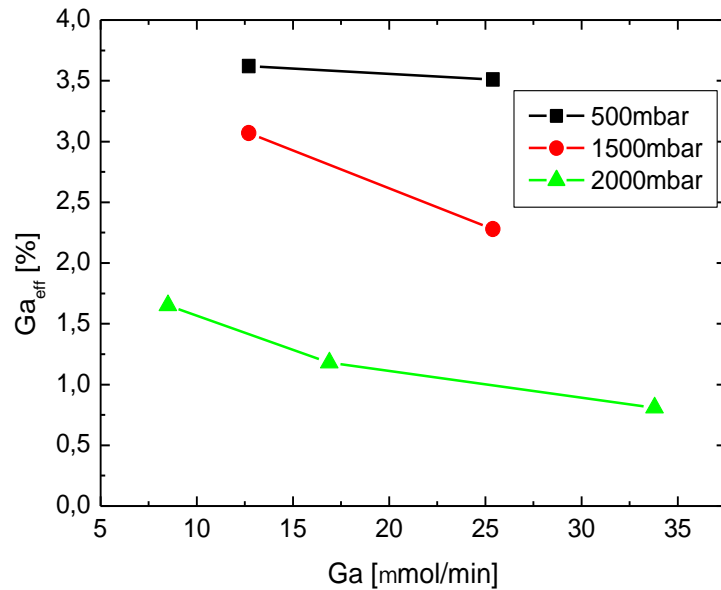


Indium increases Ga incorporation.

In incorporation efficiency increases for:

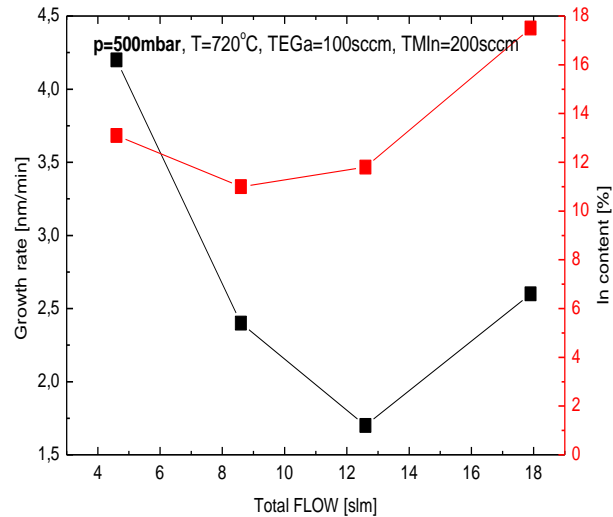
- * **lower TMIn-flow**
- * **lower temperature**
- * **higher pressure (seems to be a maximum)**

Efficiency of Ga and In incorporation into InGaN in HP

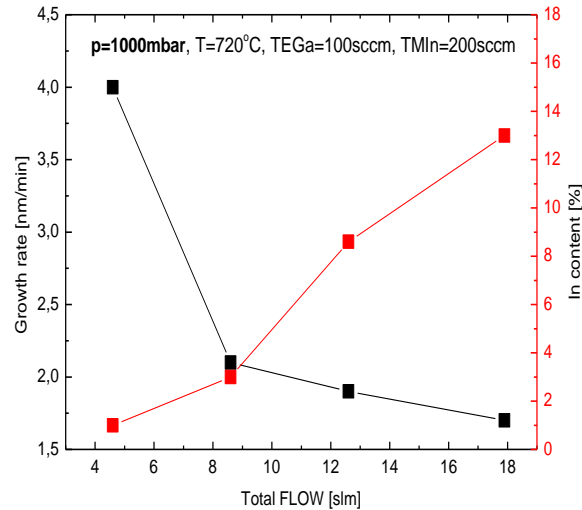


Prereactions in HP reactor- main source of troubles

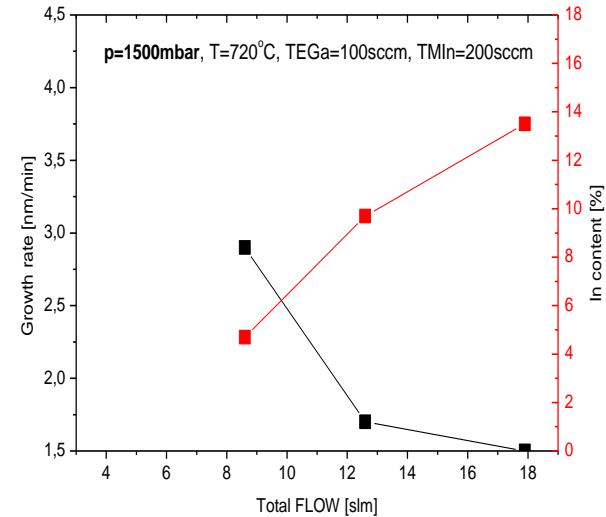
Influence of total flow on the InGaN growth rate and In incorporation in HP



500 mbar



1000 mbar

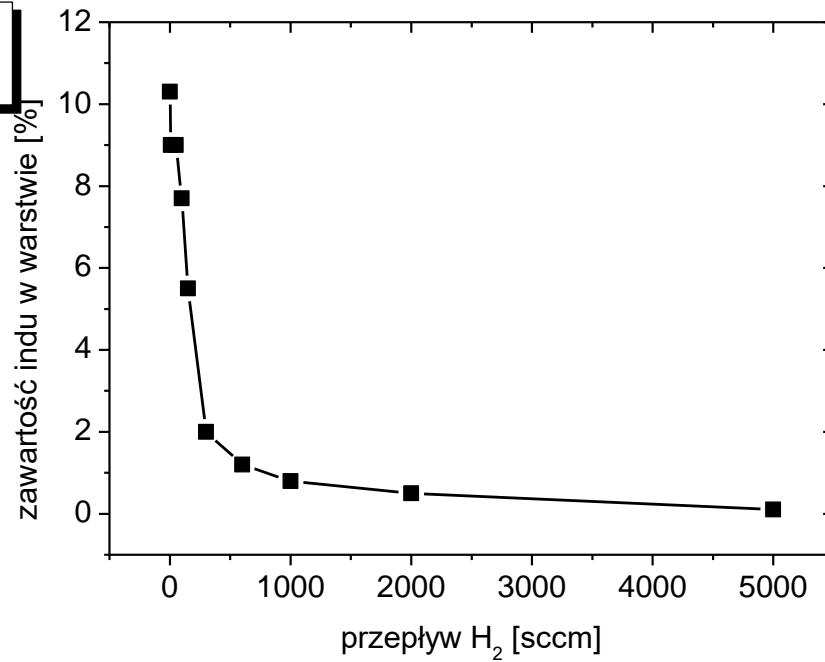
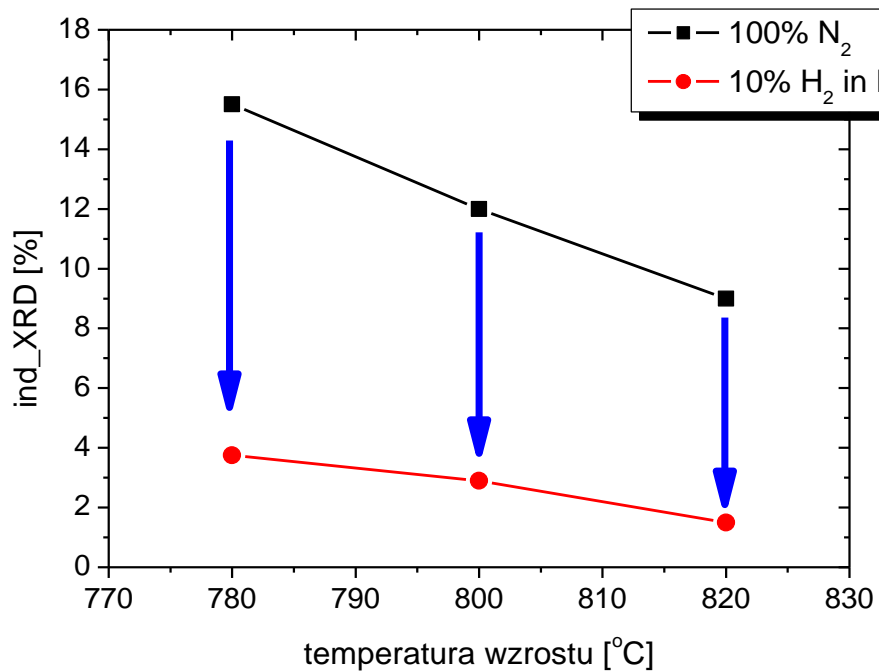


1500 mbar

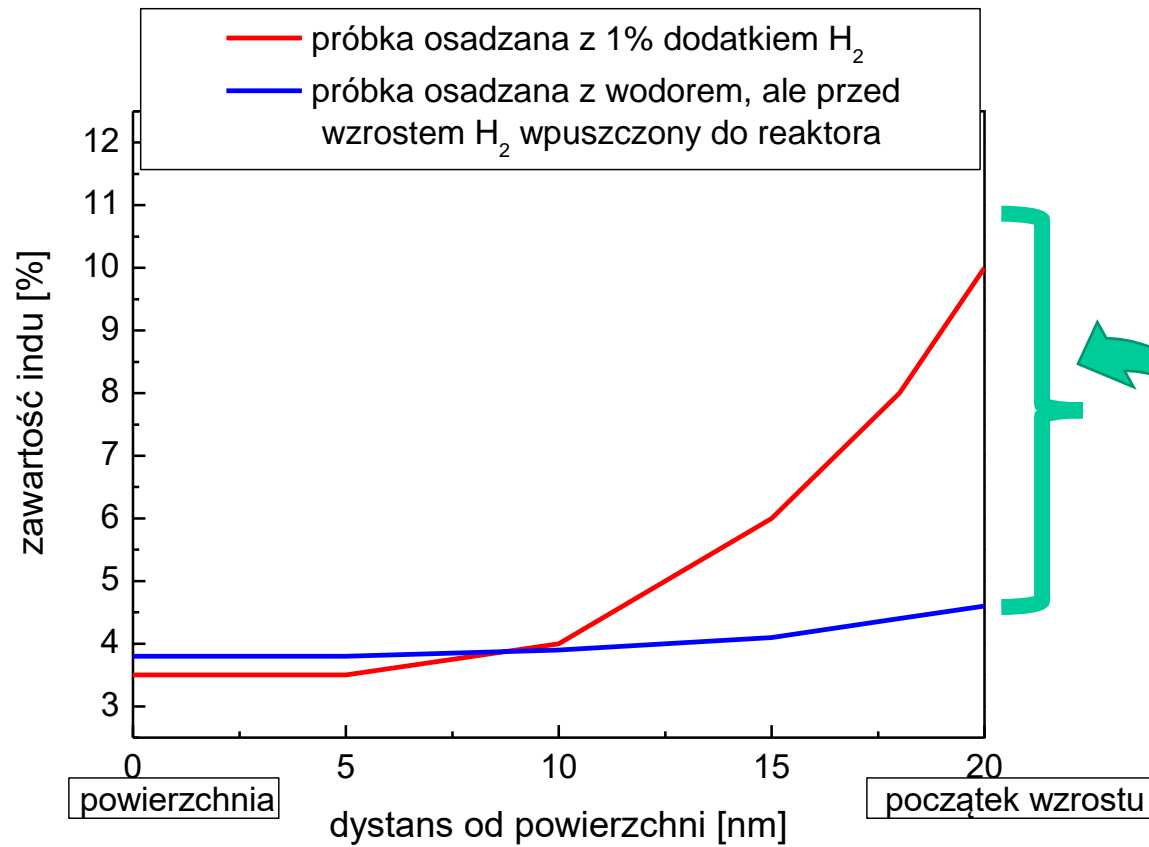
Growth rate decreases with total flow- TEGa and TMIn are blown away more efficiently

In content increases. Lower real temperature? Different NH₃/NH₂ on the surface? Lower prereaction rate?

Influence of hydrogen used in the carrier gas

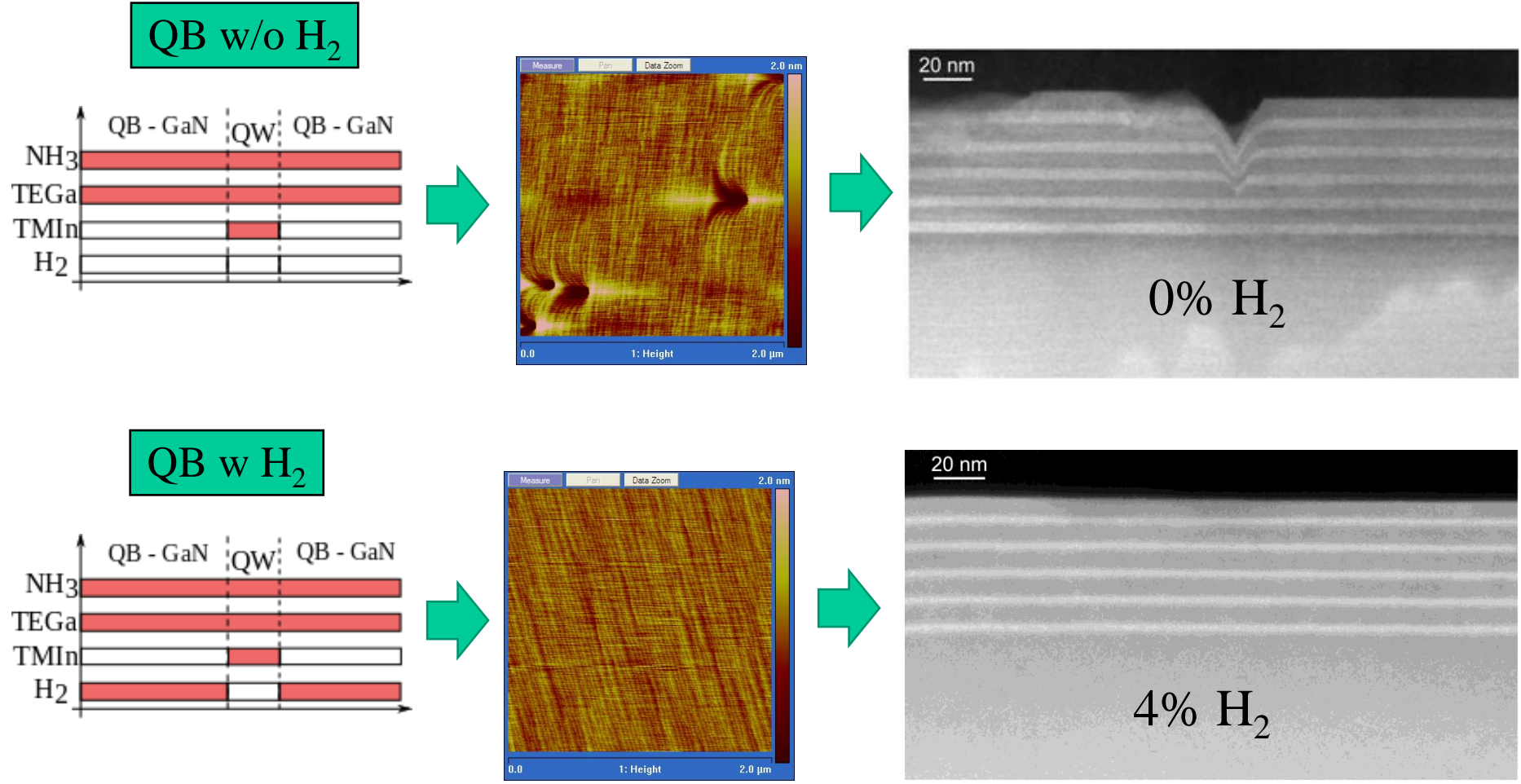


Gradient of In content in InGaN layers grown with H₂ in the carrier gas



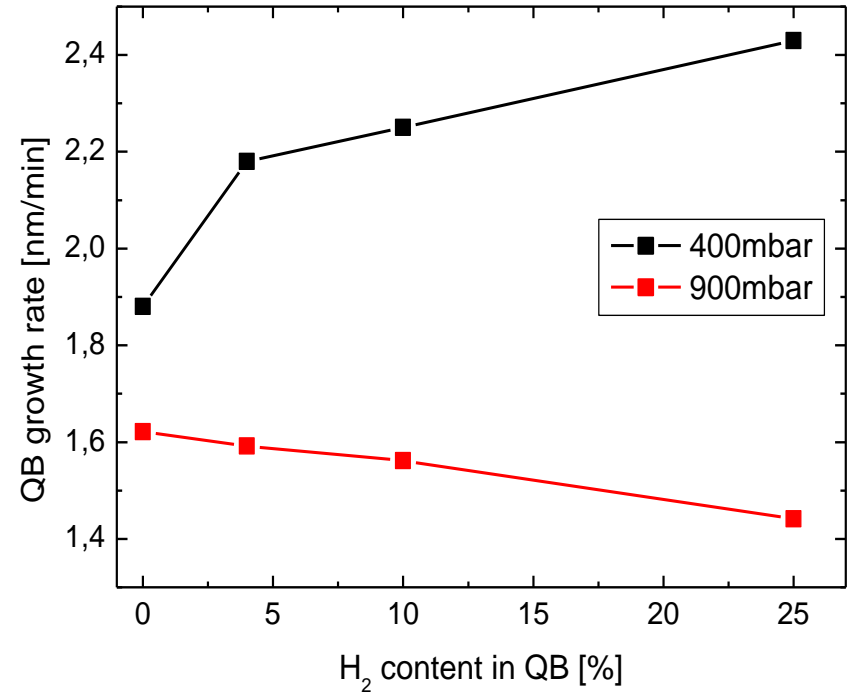
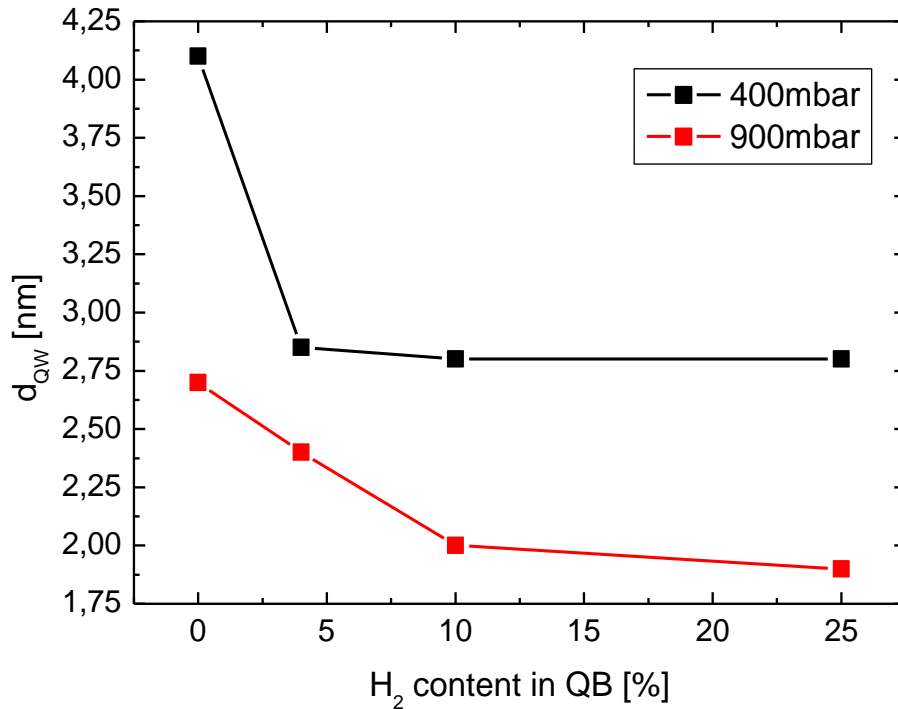
Hydrogen passivates the surface and In is not incorporated

Growth of InGaN QWs with QBs grown with hydrogen



Hydrogen eliminates defects but influences also the QWs

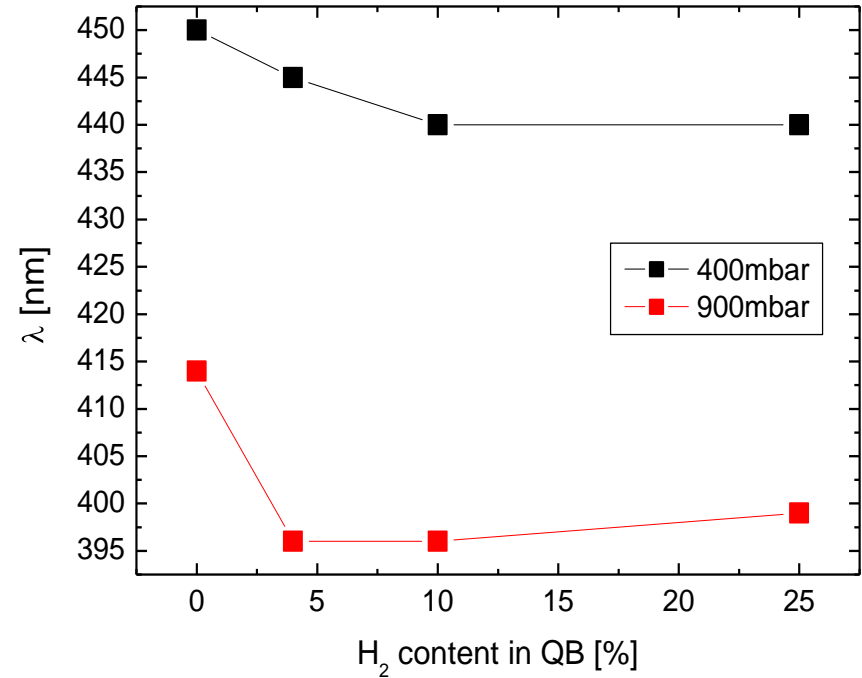
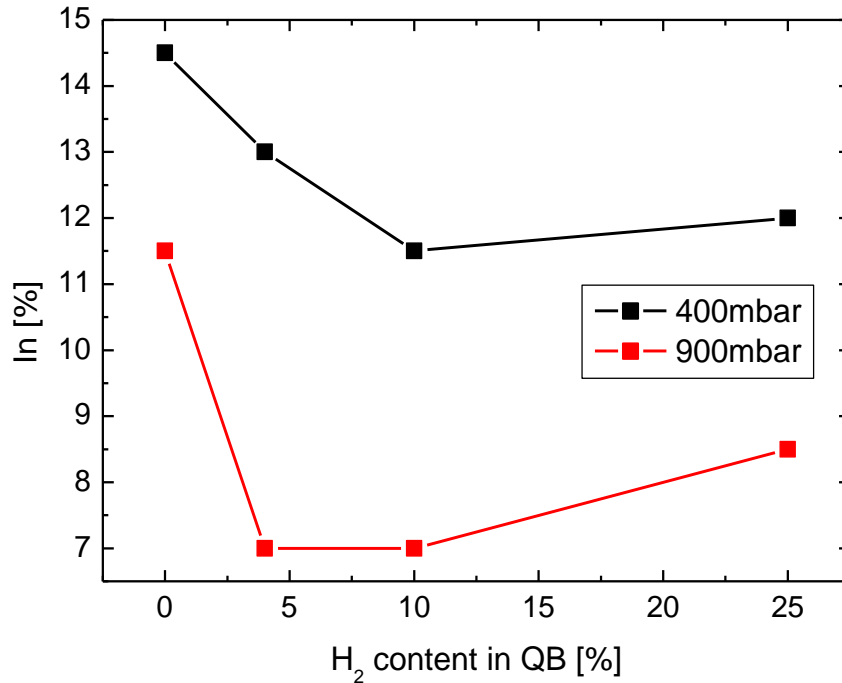
Influence of hydrogen used in the carrier gas during GaN barrier growth in CCS



Hydrogen used in QB growth etches off InGaN QW more efficiently at high pressure

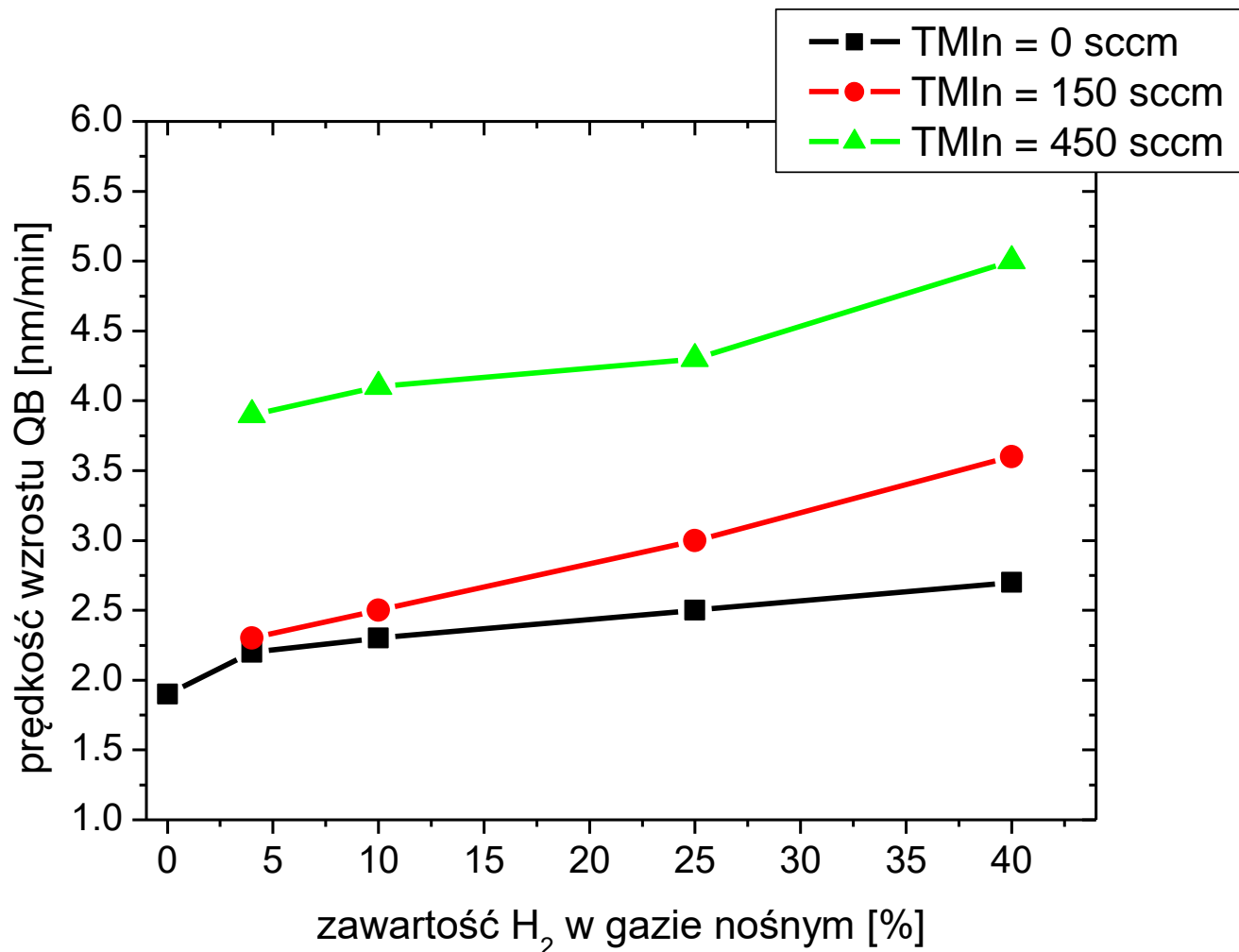
Hydrogen increases the growth rate of GaN (QB) at low pressure (???), decreases at higher pressure.

Influence of hydrogen used in the carrier gas during GaN barrier growth in CCS



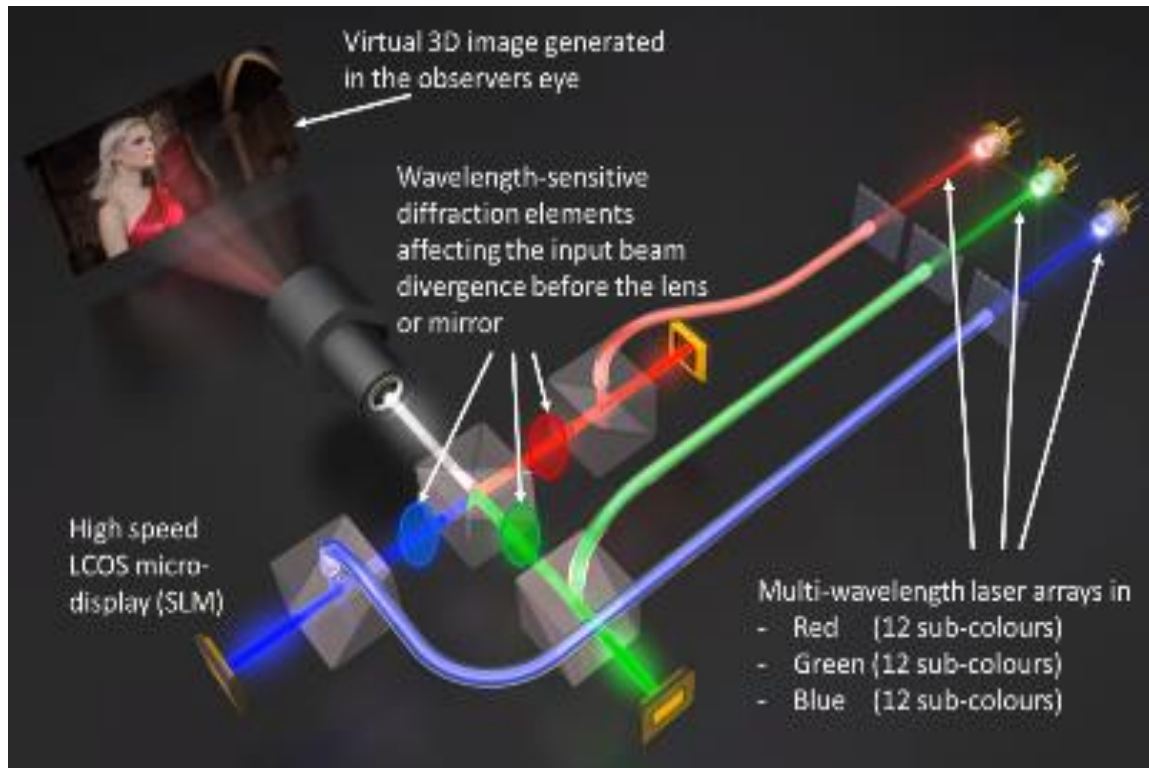
Hydrogen used in QB growth etches In off InGaN QW more efficiently at high pressure

Influence of hydrogen and H2 on Ga incorporation



Effectiveness of Ga incorporation in CCS

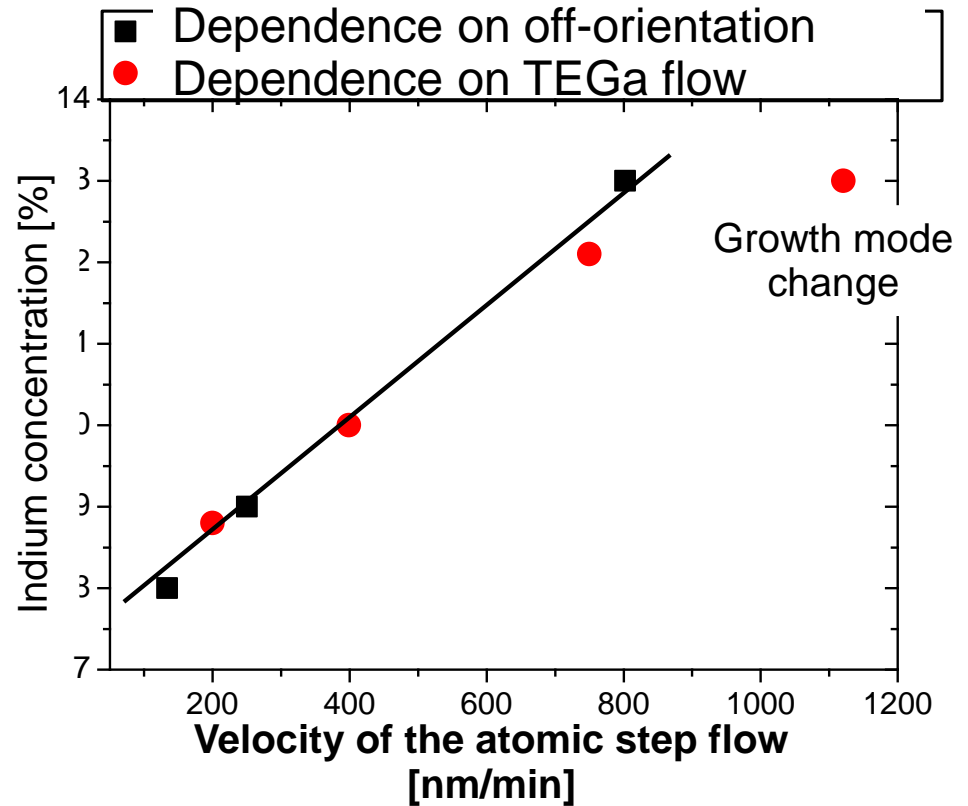
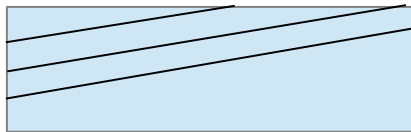
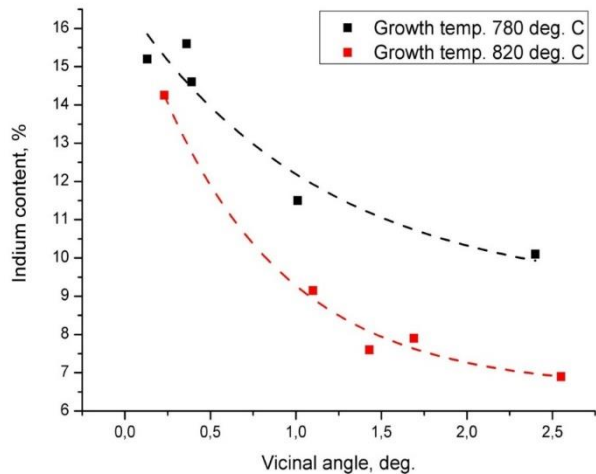
3-D Projectors without goggles- Holy Grail of optoelectronics



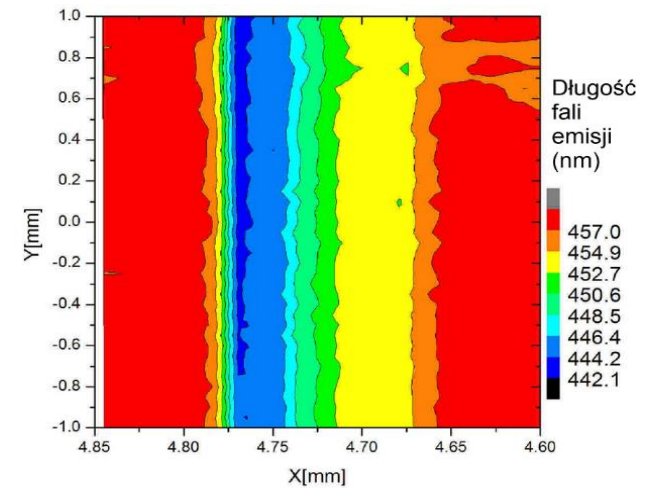
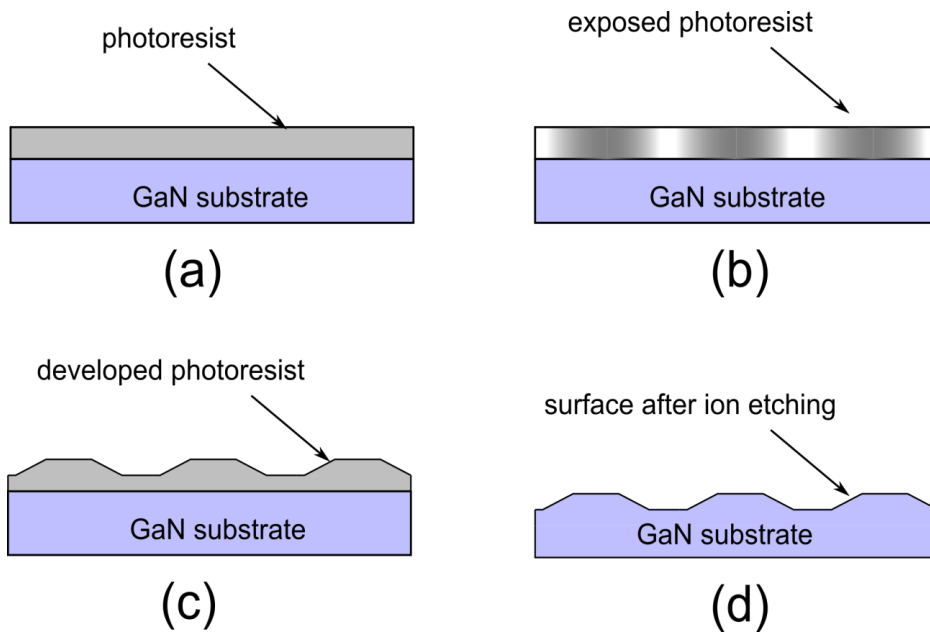
Nitrides:
Blue 450-460 nm,
step 1 nm
Green 520-530 nm,
step 1 nm

Arsenides/phosphid
es
Red 630-640 nm,
step 1 nm

In incorporation into InGaN layers versus GaN substrate off-orientation or growth rate

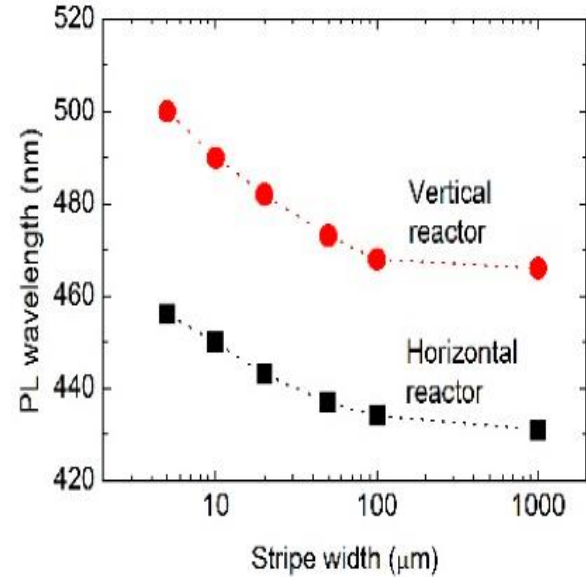
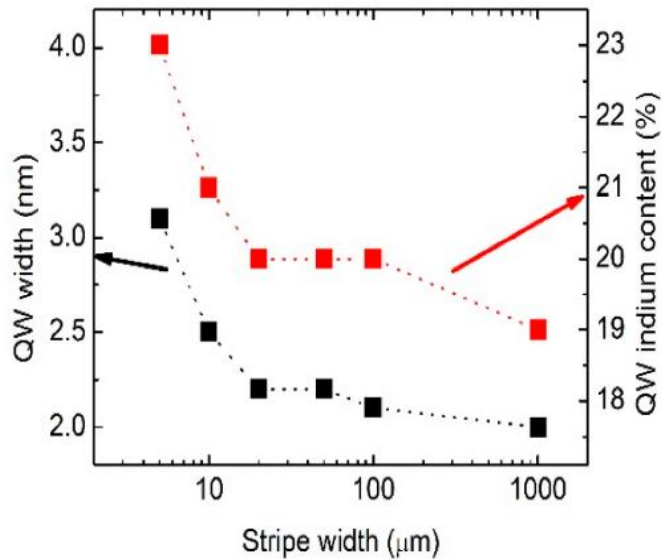
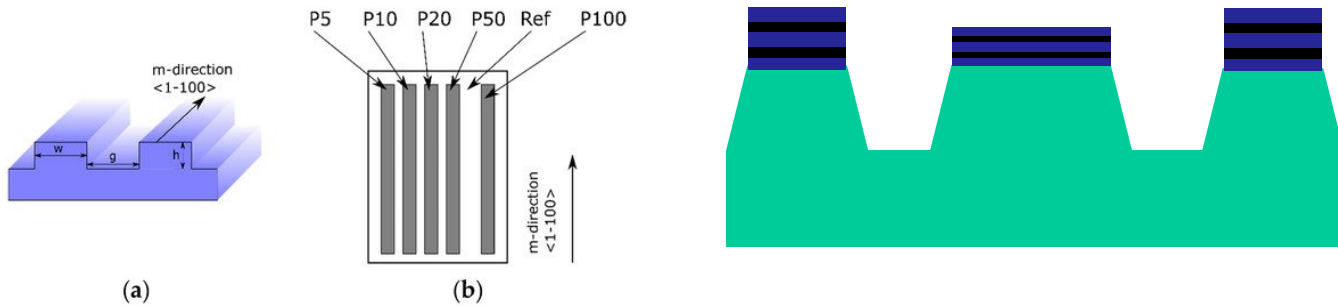


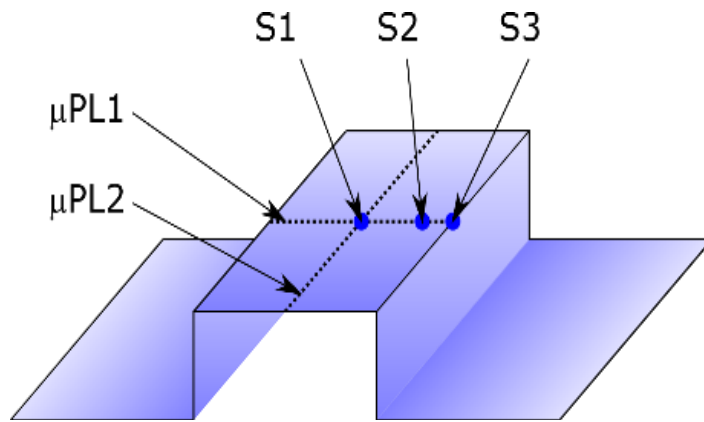
Technology 1: Lateral patterning



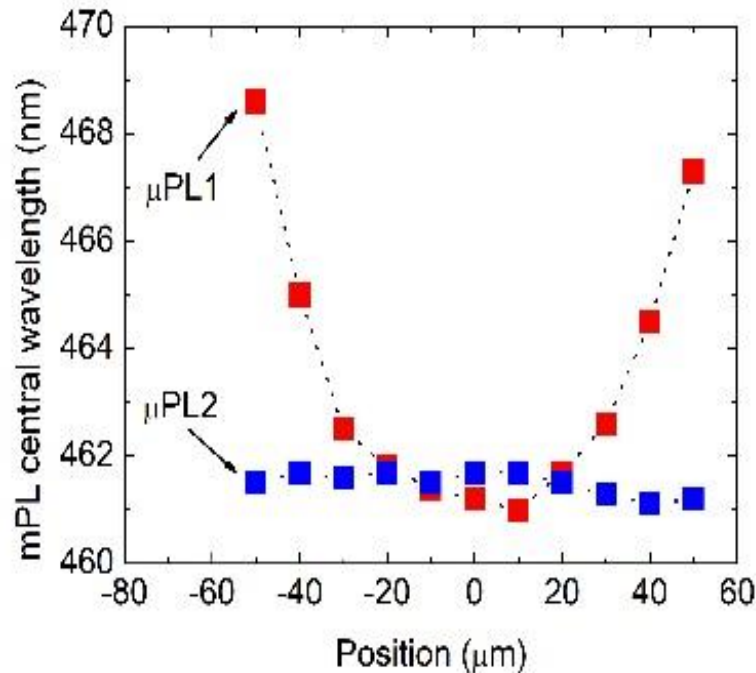
M. Sarzynski idea
Patented by TopGaN/Unipress

Technology 2. Growth of InGaN QWs on narrow stripes.





Faster growth at the edges, more indium incorporated

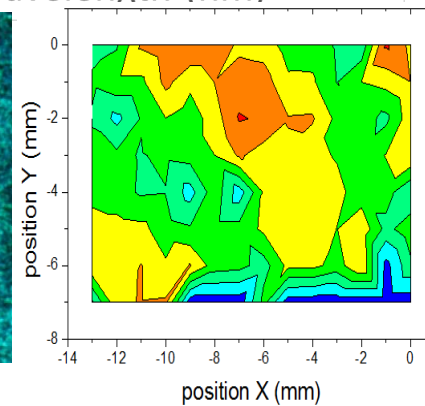
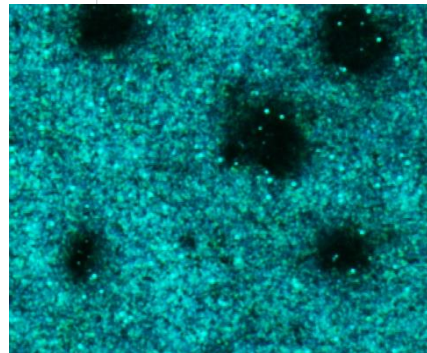
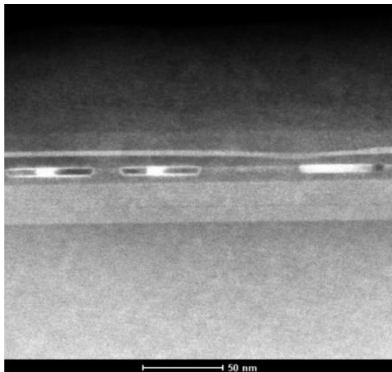
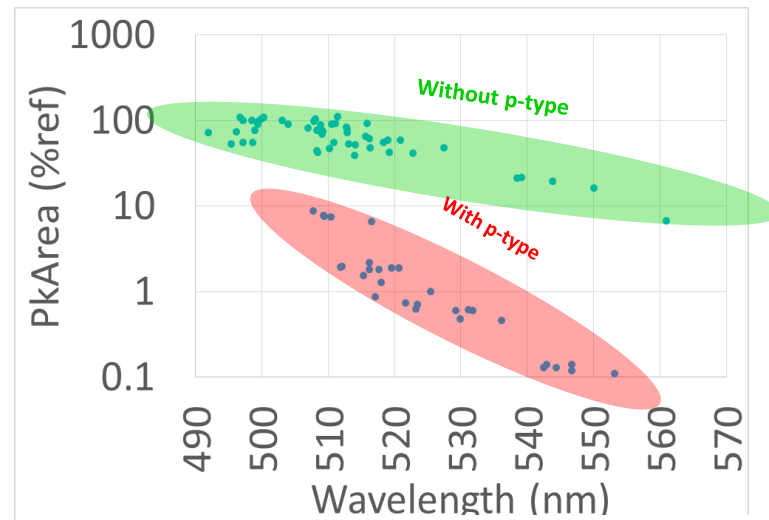


Both technology 1 and 2 of blue multicolour arrays attract a big interest as they may lead to 3D projectors.

Decomposition and homogenization of InGaN QWs at high temperature

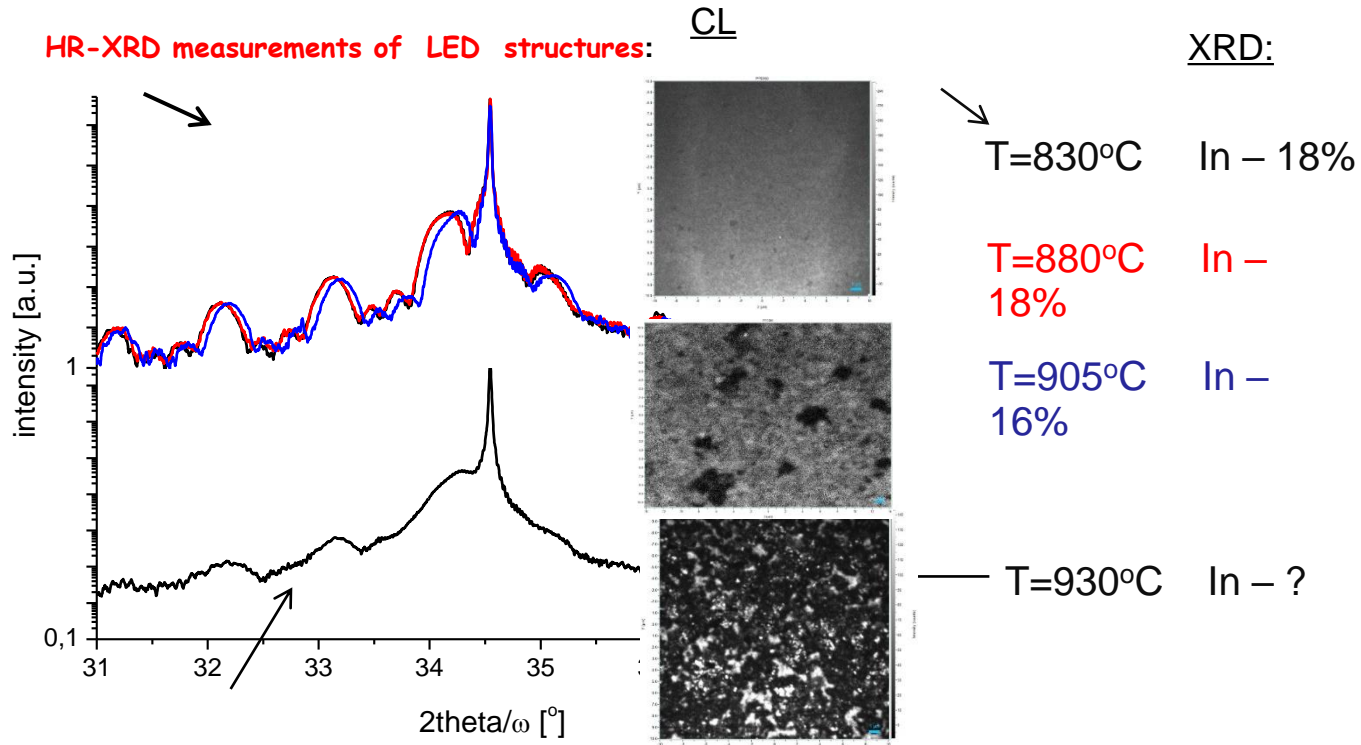
GaN:Mg	$T_{Gr} = XXXX^{\circ}C$
AlGaN:Mg	
GaN:Mg	
EBL - AlGaN:Mg	
Cap - GaN	
Cap - GaN	$T_{Gr} \text{ QW} < 740^{\circ}C$
QW - InGaN	
QB - GaN	$T_{Gr} \text{ QB} > 740^{\circ}C$
InGaN	
	For In content > 15%
GaN	$T_{Gr} = 1000^{\circ}C$
AlGaN:Si	
GaN:Si	
Substrate	

InGaN MQW decomposition

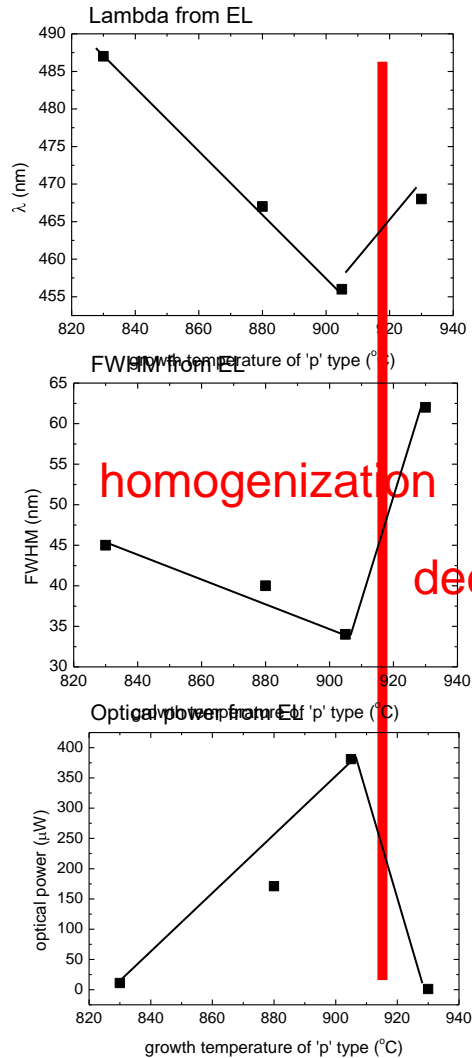


TEM: nanometer scale, Fluorescent microscopy: micrometers, MicroPL: m

Changes of the MQWs during p-type growth at high temperature: samples on sapphire



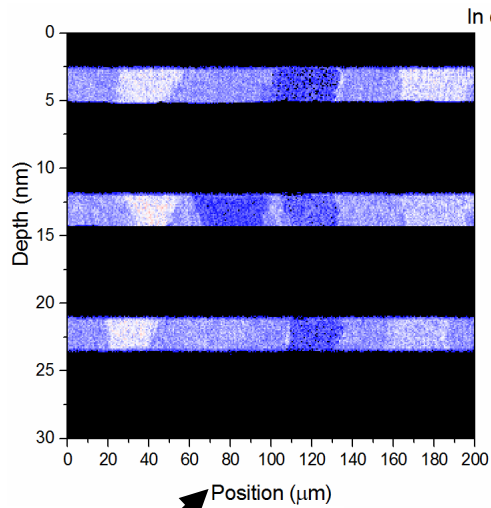
At high temperature satellite peaks becomes much more broader and disappear : QWs degradation occurs



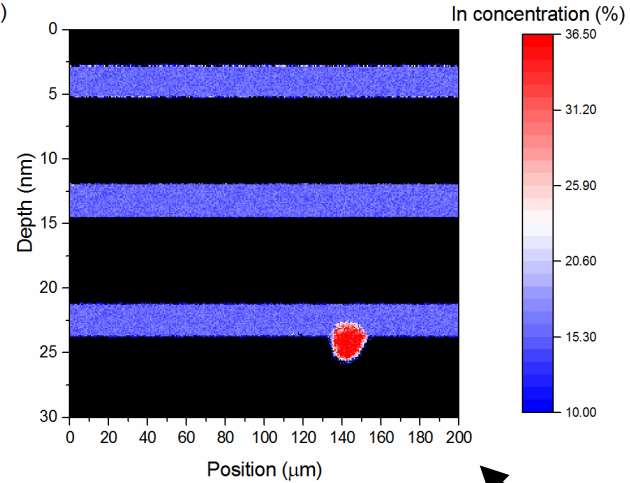
For samples on sapphire (high dislocation density) we are able to homogenize InGaN QWs by growing p-type at high temperature.

If this temperature is too high, we deal with a catastrophic damage

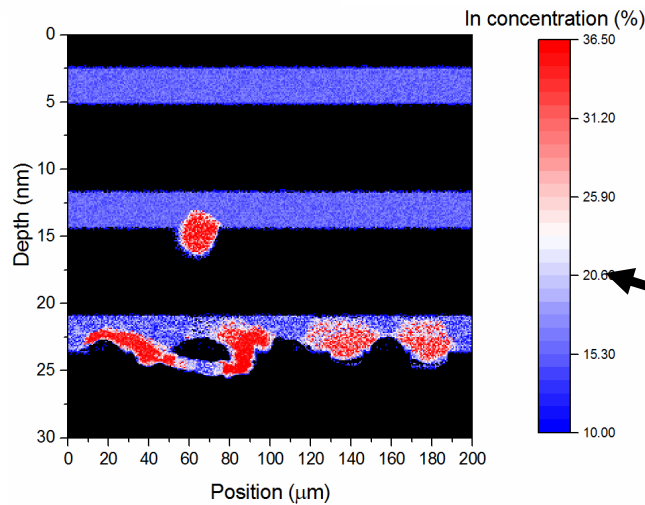
SIMS data of In-content



as grown

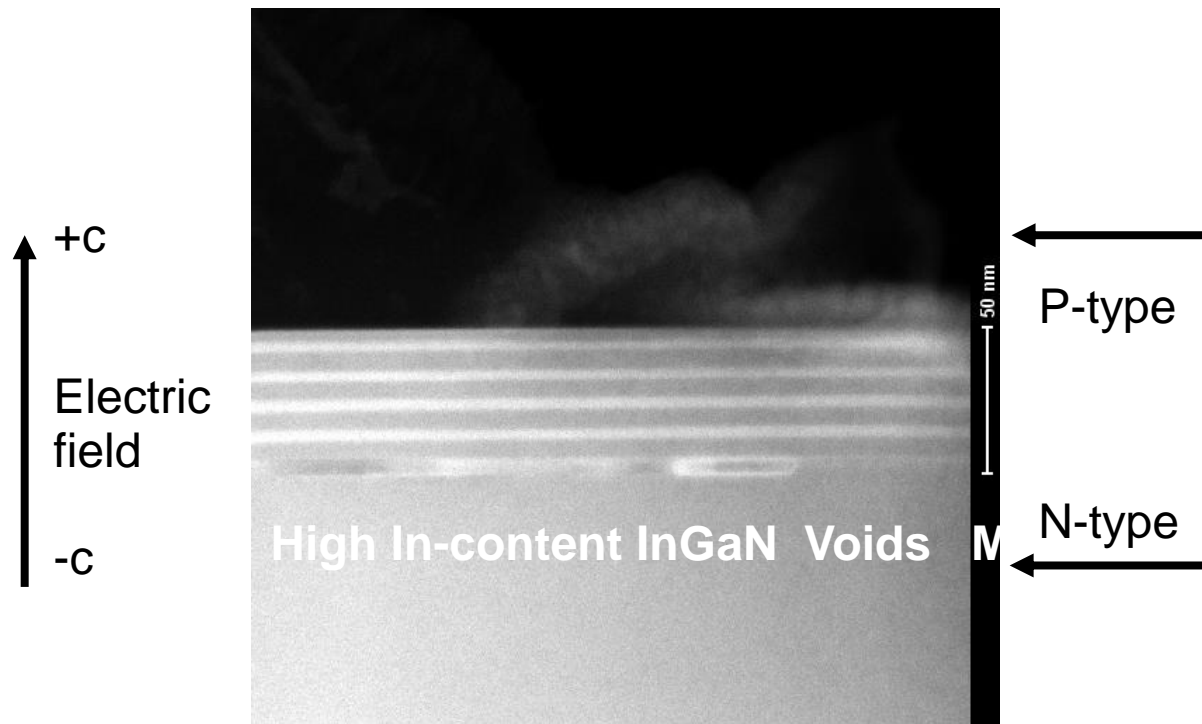


Homogenized
905°C



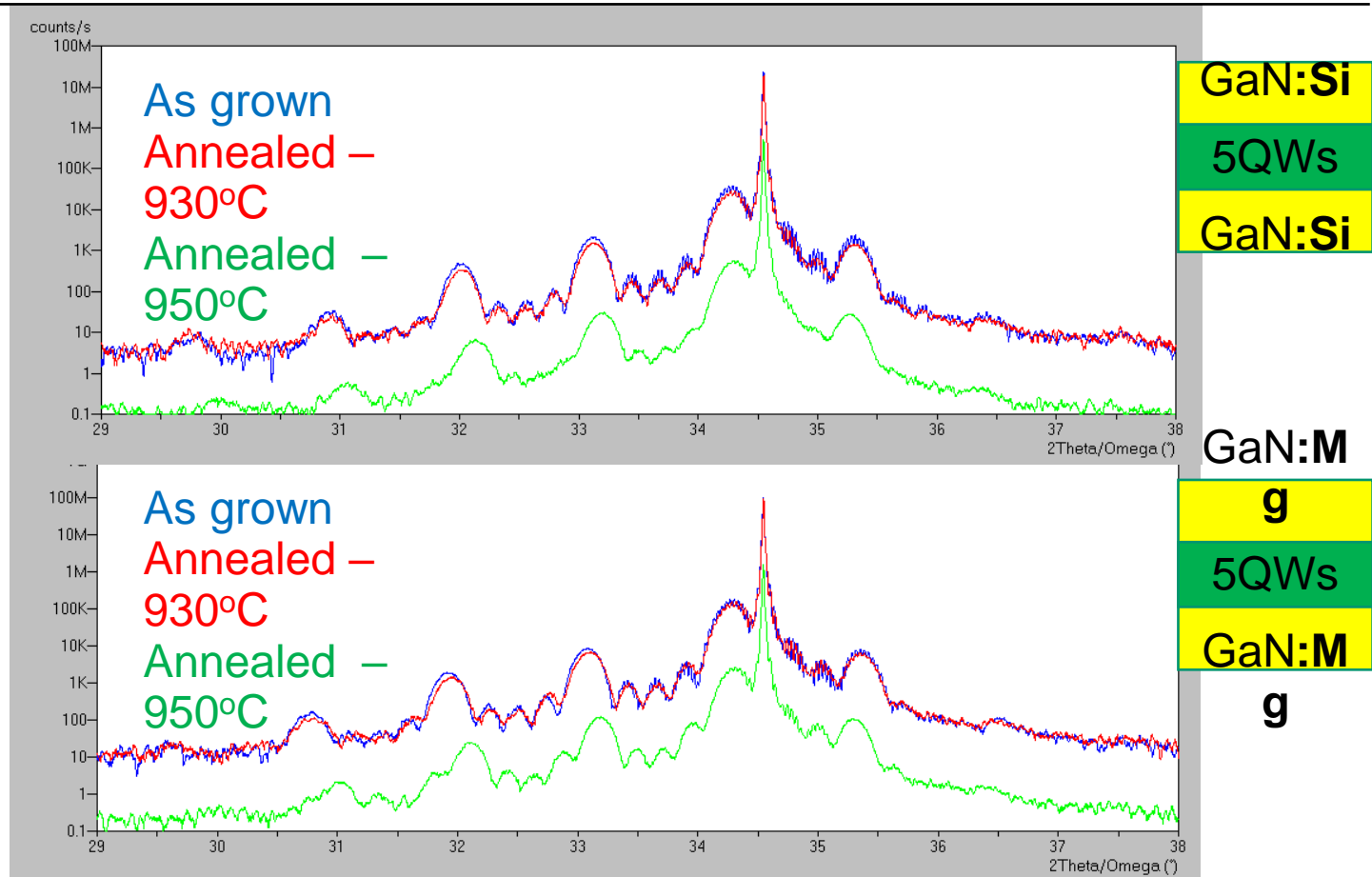
Decomposed
930°C

Why does the decomposition start from the first QW?



Diiferent doping below and above the InGaN/GaN MQWs

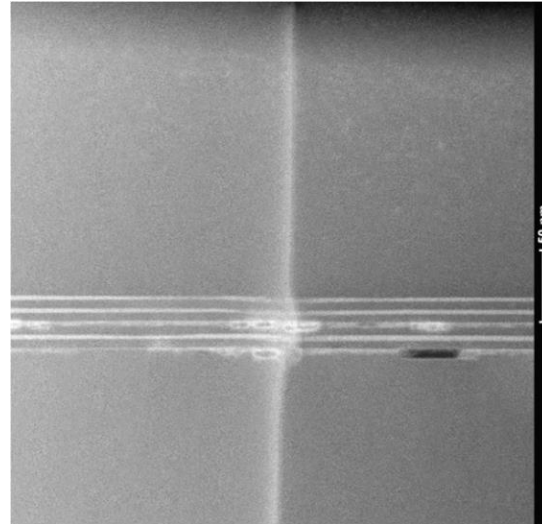
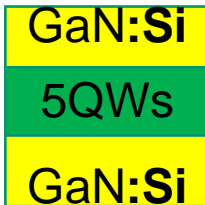
5QWs - (460 nm) - 17%In



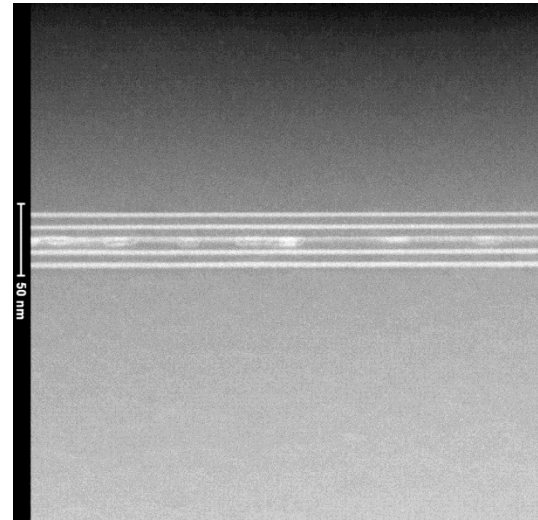
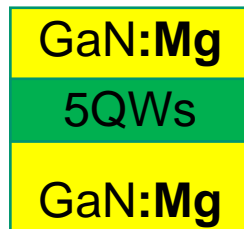
After annealing at 950°C

No decomposition from the top

Electric field
driven diffusion?
Yes!



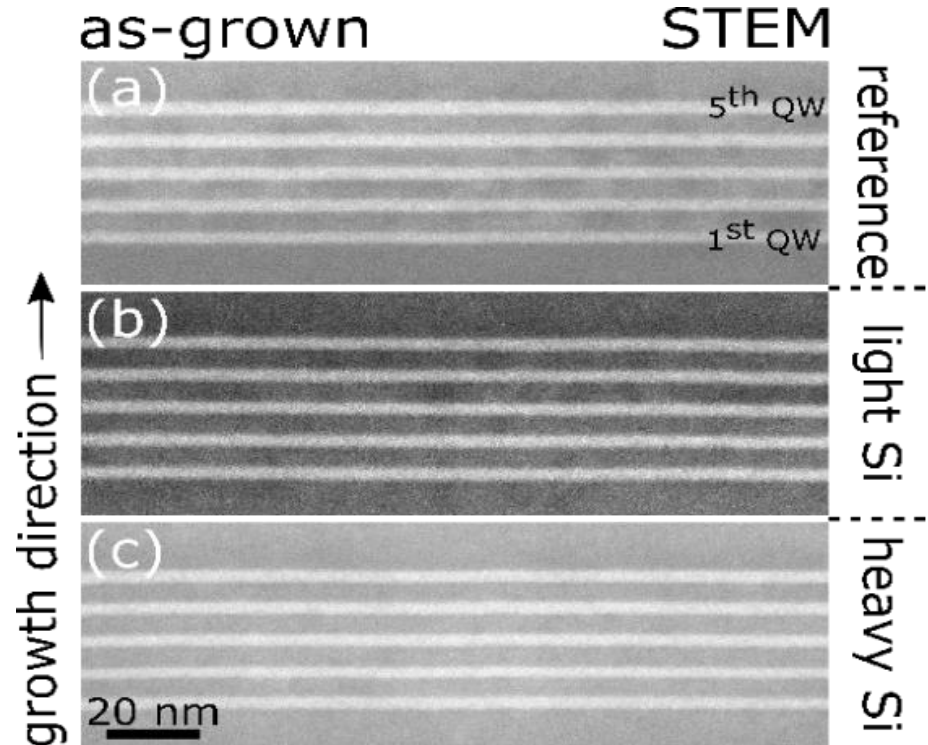
No decomposition
above and below
GaN:Mg



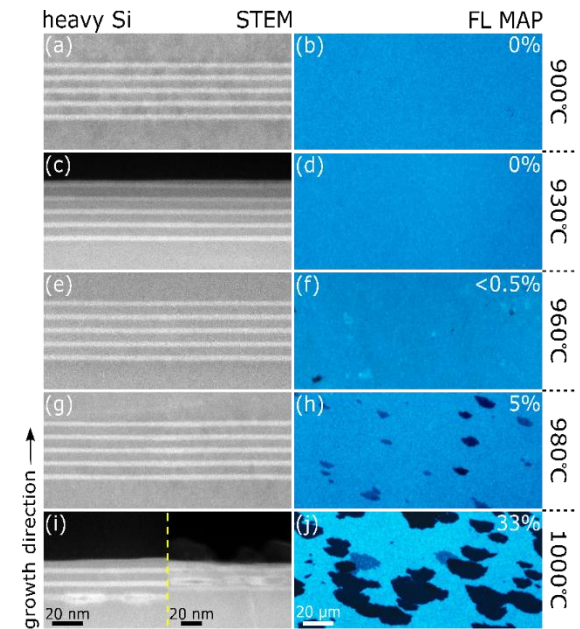
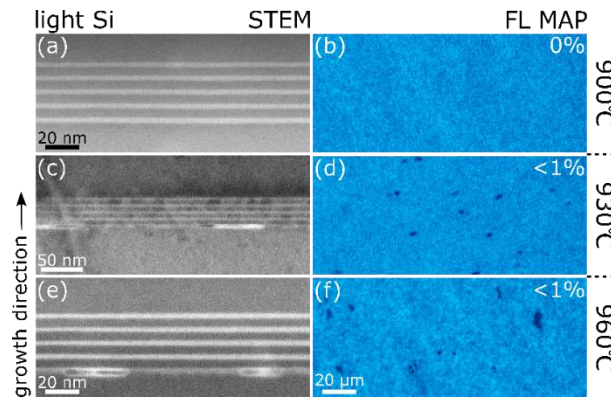
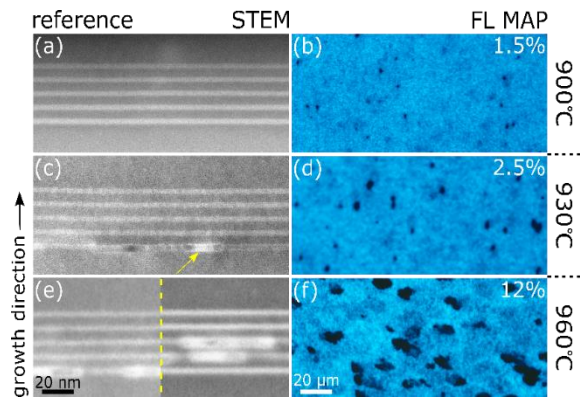
Ga-vacancies?
Yes!

Influence of Si-doping on InGaN QW decomposition

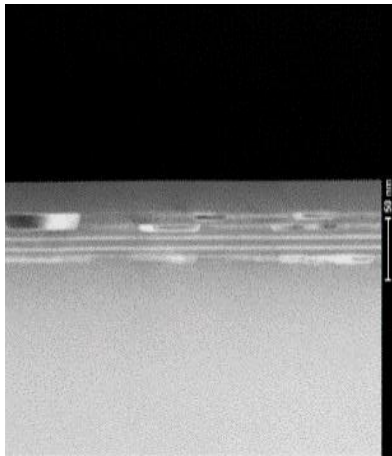
cap	80nm GaN	850°C
BL	4.5nm GaN: X	810°C
QW	2.5nm In _{0.16} GaN	730°C
BL	4.5nm GaN: X	810°C
n-type	500nm GaN:Si	980°C
buffer	1.5μm GaN	1050°C
nucleation layer	100nm GaN	
	(0001) sapphire	
structure	X doping in BLs	
reference	unintentional	
light Si	Si 10 ¹⁸ cm ⁻³	
heavy Si	Si 10 ¹⁹ cm ⁻³	



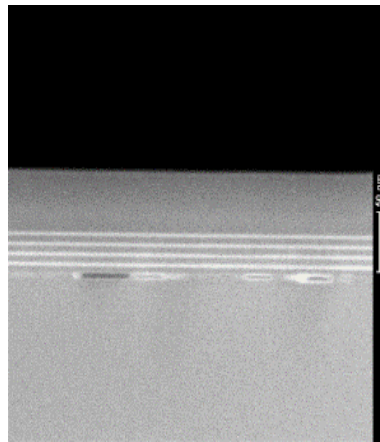
High Si doping: decrease of V(Ga) mobility



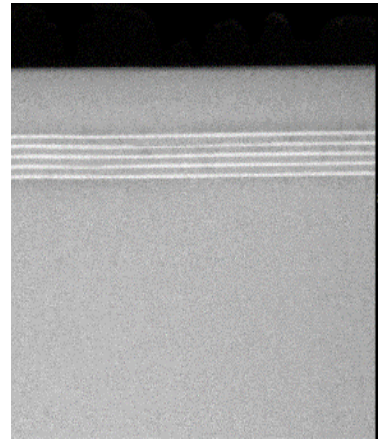
Influence of annealing atmosphere



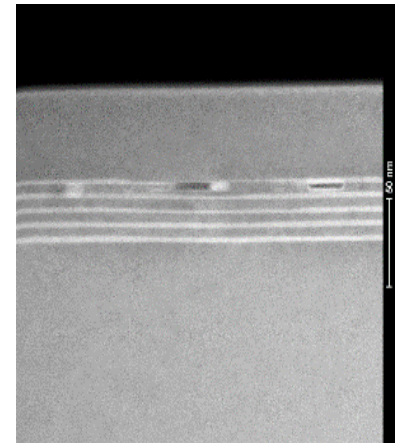
A



B



C



D

TEM topographs of InGaN/GaN QWs after annealing for 30 min. at 940°C and

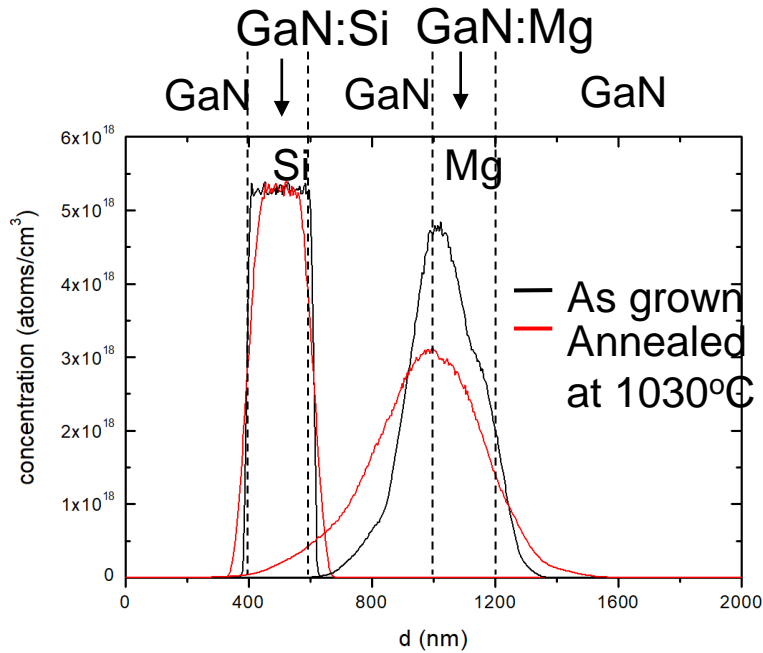
A: in NH₃+H₂ atmosphere,

B: in TEGa+NH₃+H₂,

C: in TEGa+NH₃+H₂, the barrier before the first QW doped with Si,

D: in NH₃+H₂, the barrier before the first QW doped with Si.

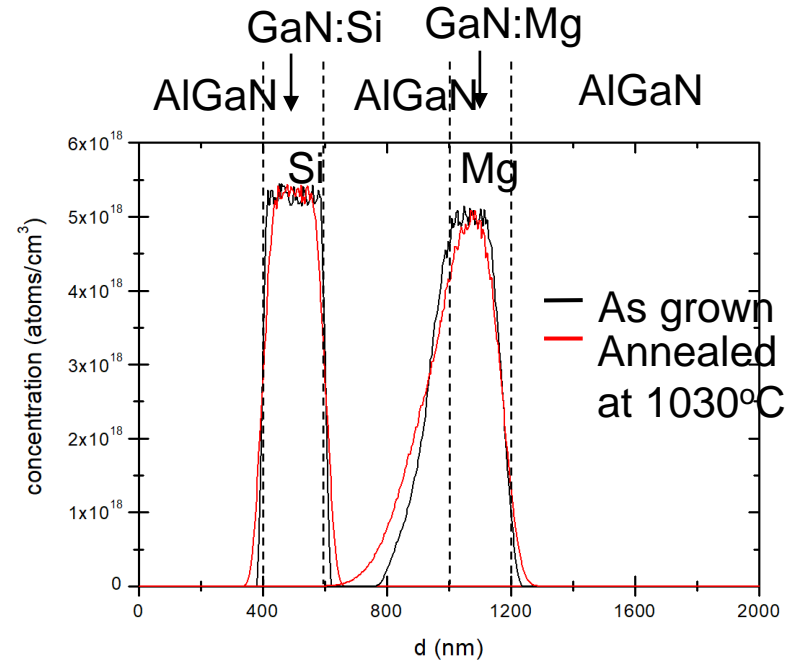
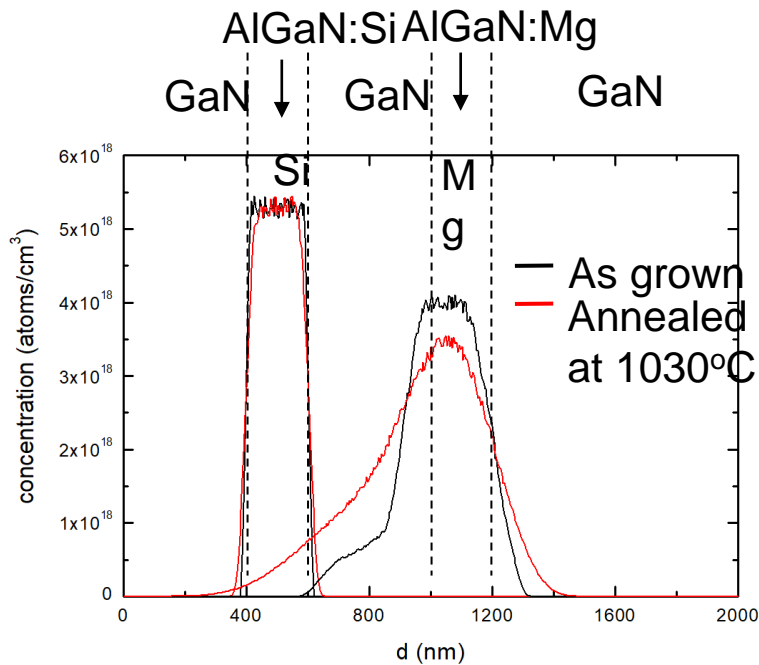
Atoms diffuse during growth!



Why Mg diffuses easier than Si?
Interaction of Mg, H, V?

Reactor memory. Why Mg is better remembered than Si?

Mg diffuses easier in GaN than in AlGaN?



Closing remarks

1. The growth parameters in MOVPE are not independent to each other.
2. Growth is different in different reactors.
3. Incorporation of atoms is still not well understood.
4. The properties of the layers depend what has been grown below them and above them.